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Luo et al.

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(54) **INTEGRATED ASSEMBLIES AND METHODS OF FORMING INTEGRATED ASSEMBLIES**

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H01L 27/11556 (2017.01)
H01L 27/11524 (2017.01)

(52) **U.S. Cl.**
 CPC **H01L 27/11582** (2013.01); **H01L 27/1157** (2013.01); **H01L 27/11524** (2013.01); **H01L 27/11556** (2013.01)

(58) **Field of Classification Search**
 None
 See application file for complete search history.

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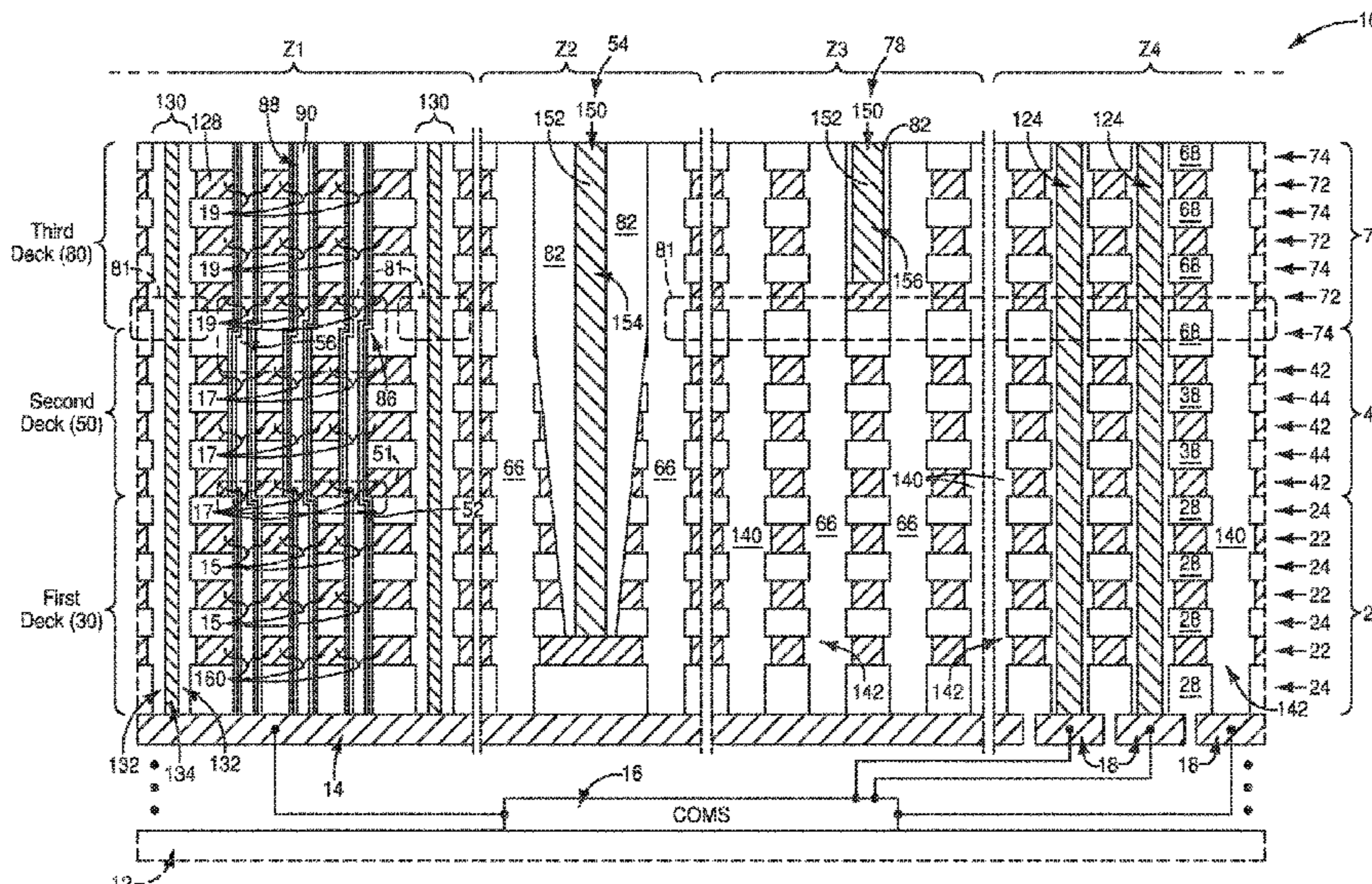
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(57) **ABSTRACT**

Some embodiments include an integrated assembly having a first deck, a second deck over the first deck, and a third deck over the second deck. The first deck has first conductive levels disposed one atop another. The second deck has second conductive levels disposed one atop another. The third deck has third conductive levels disposed one atop another. A first staircase region extends to the first and second conductive levels, and passes through the third conductive levels. A second staircase region extends to the third conductive levels and not to the first and second conductive levels. Some embodiments include methods of forming integrated assemblies.

25 Claims, 34 Drawing Sheets



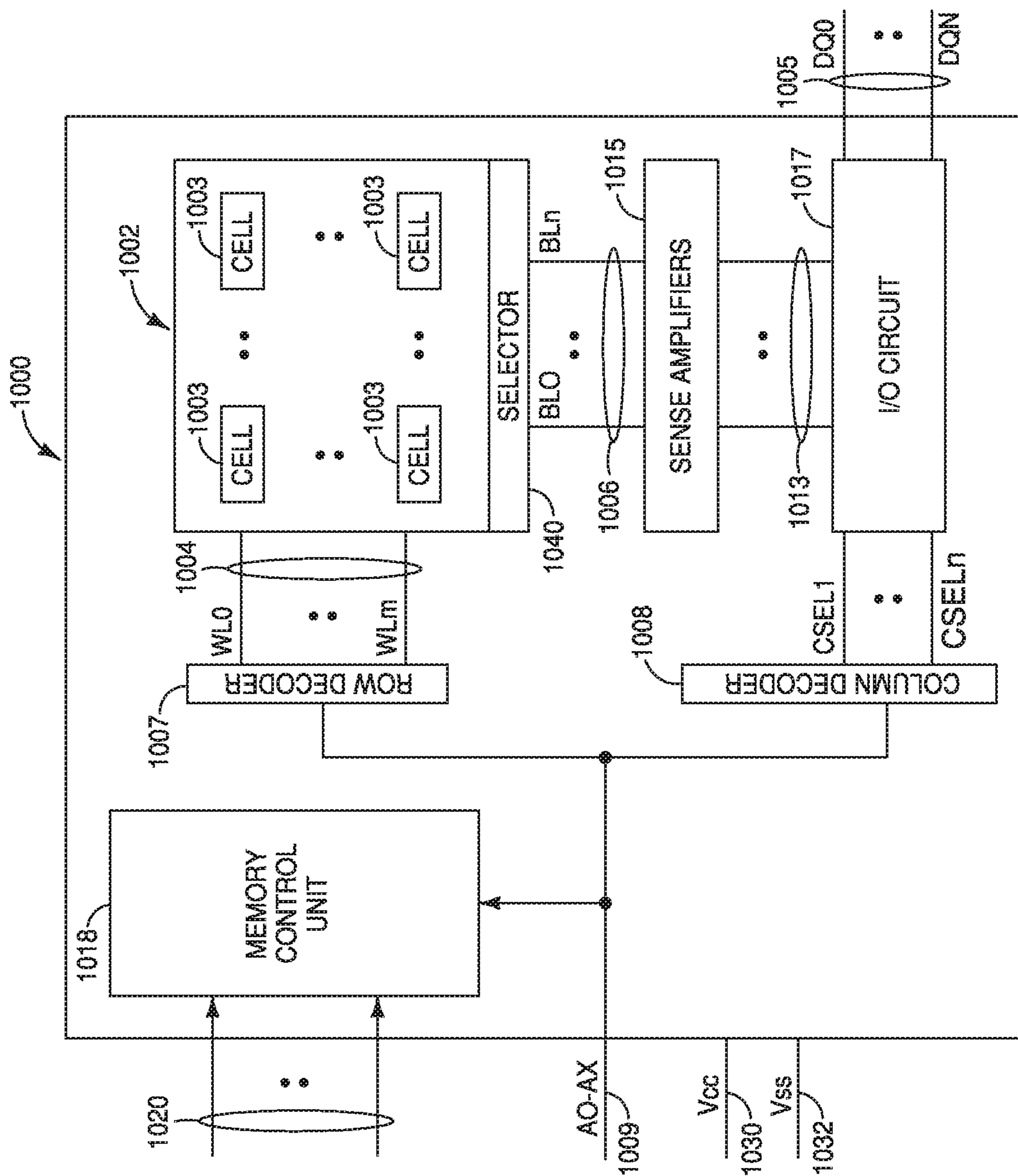
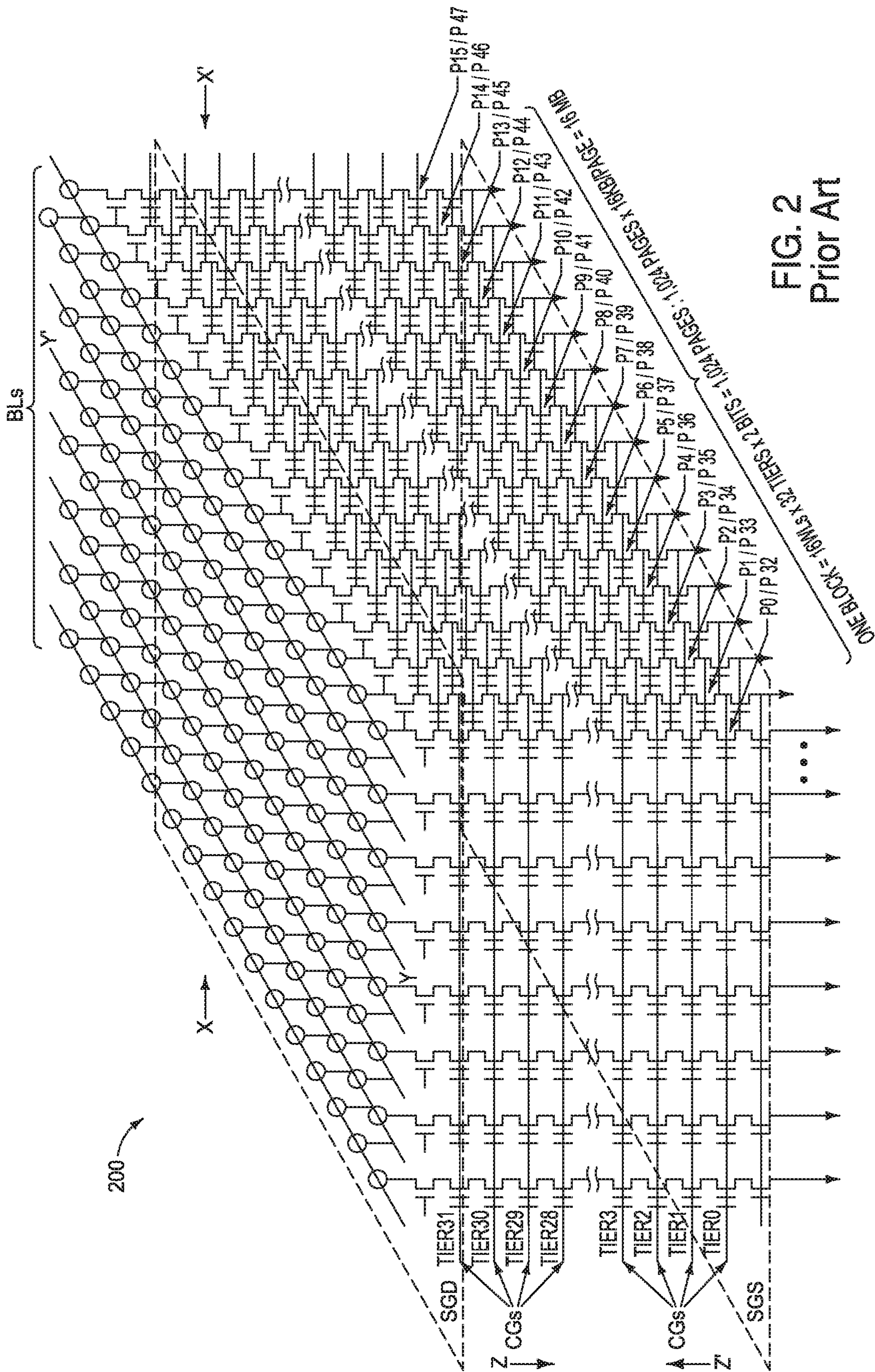


FIG. 1
Prior Art



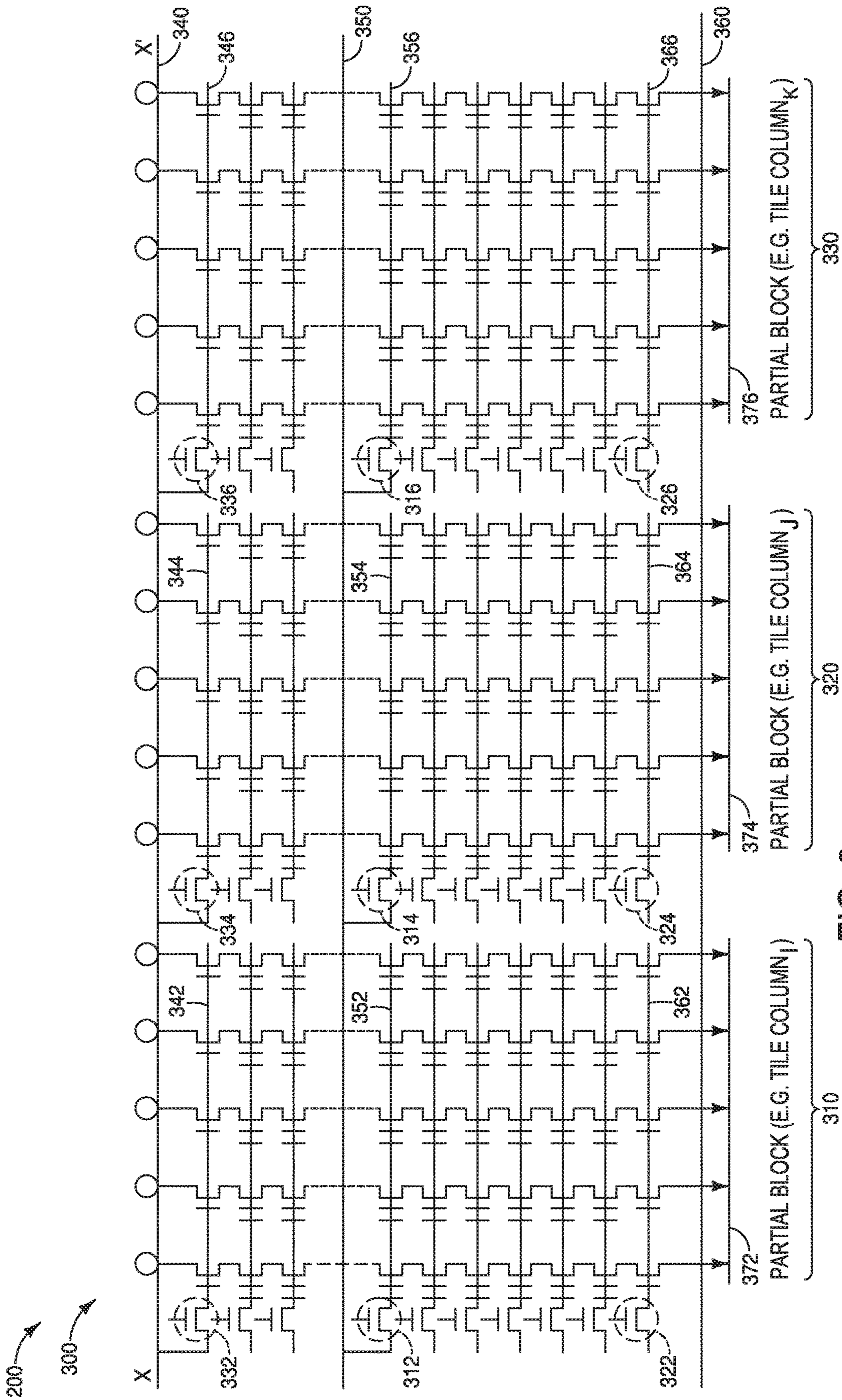


FIG. 3
Prior Art

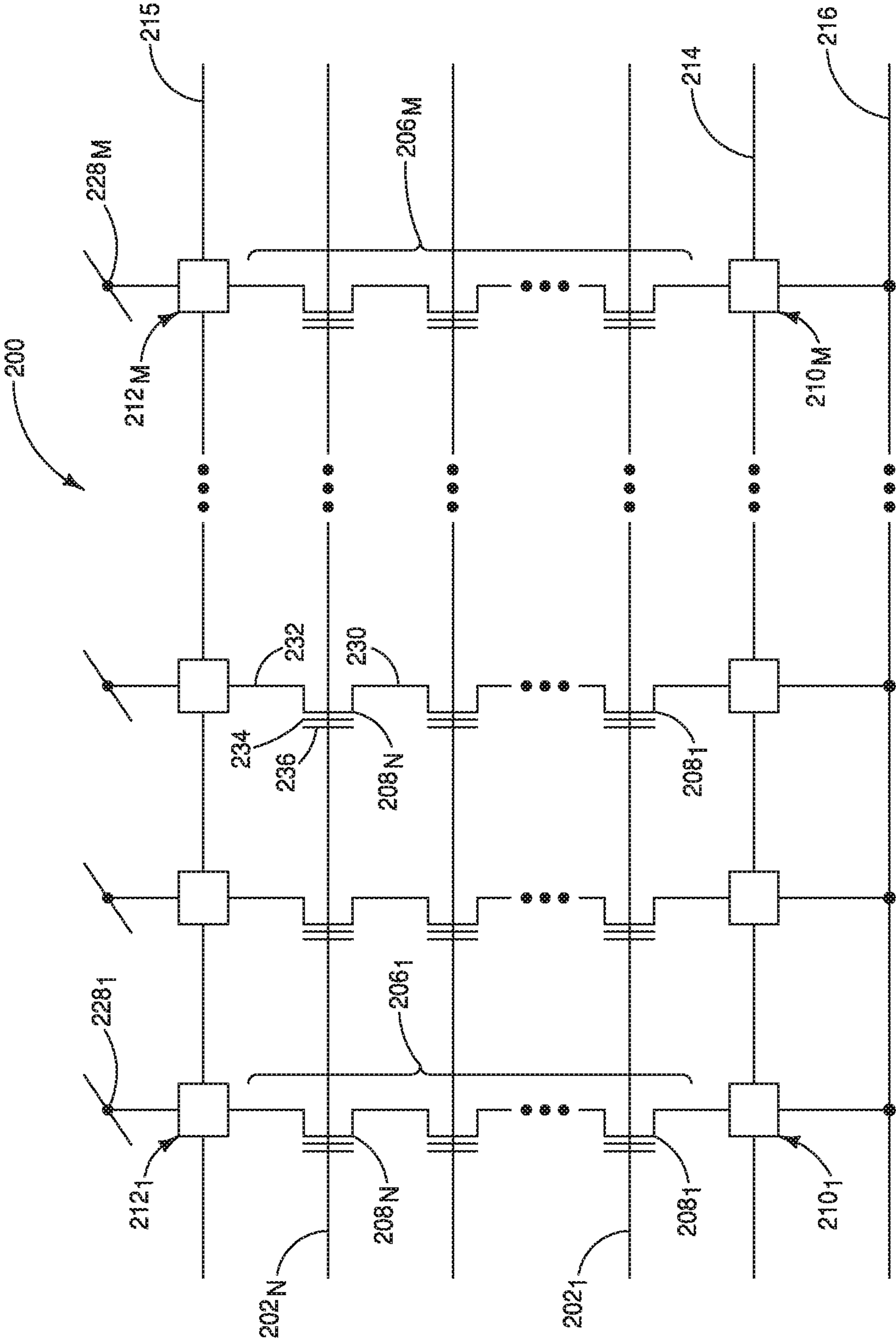
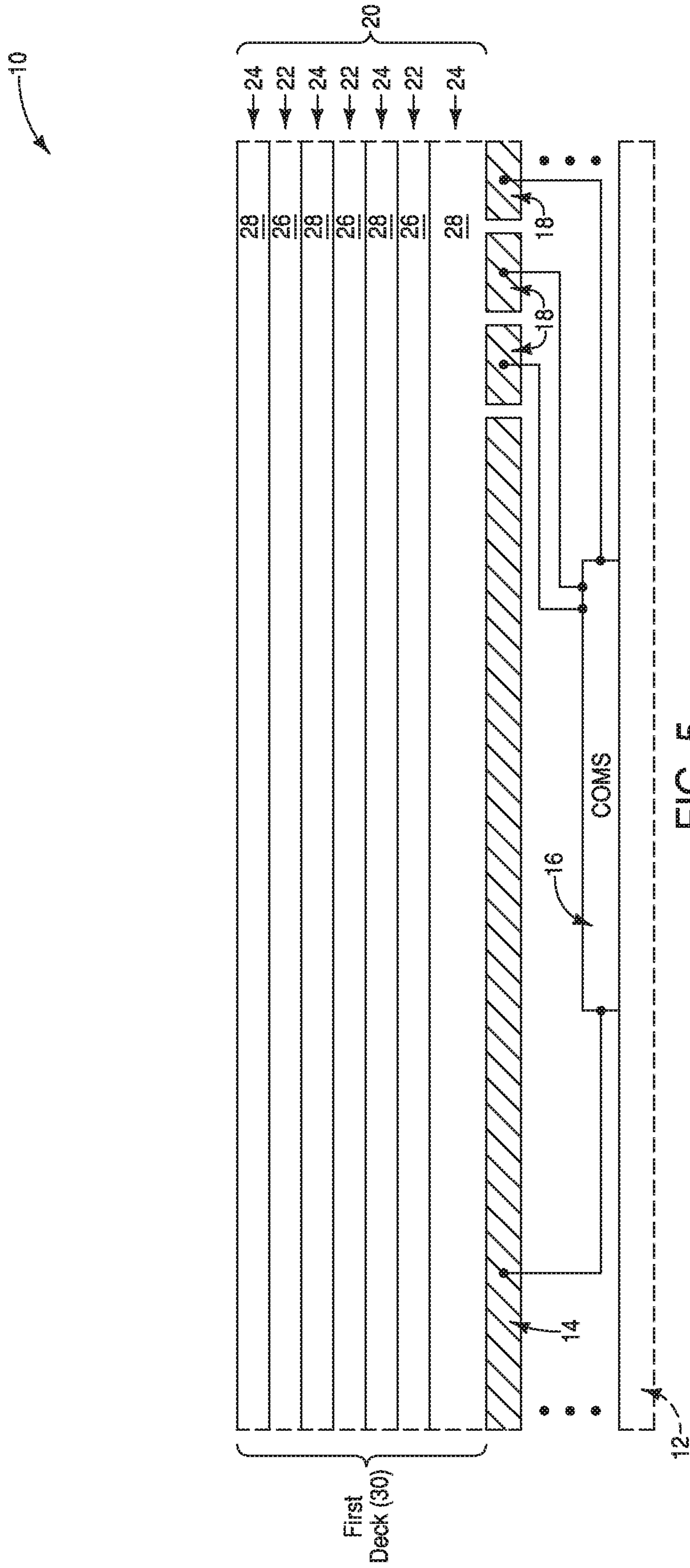


FIG. 4
Prior Art



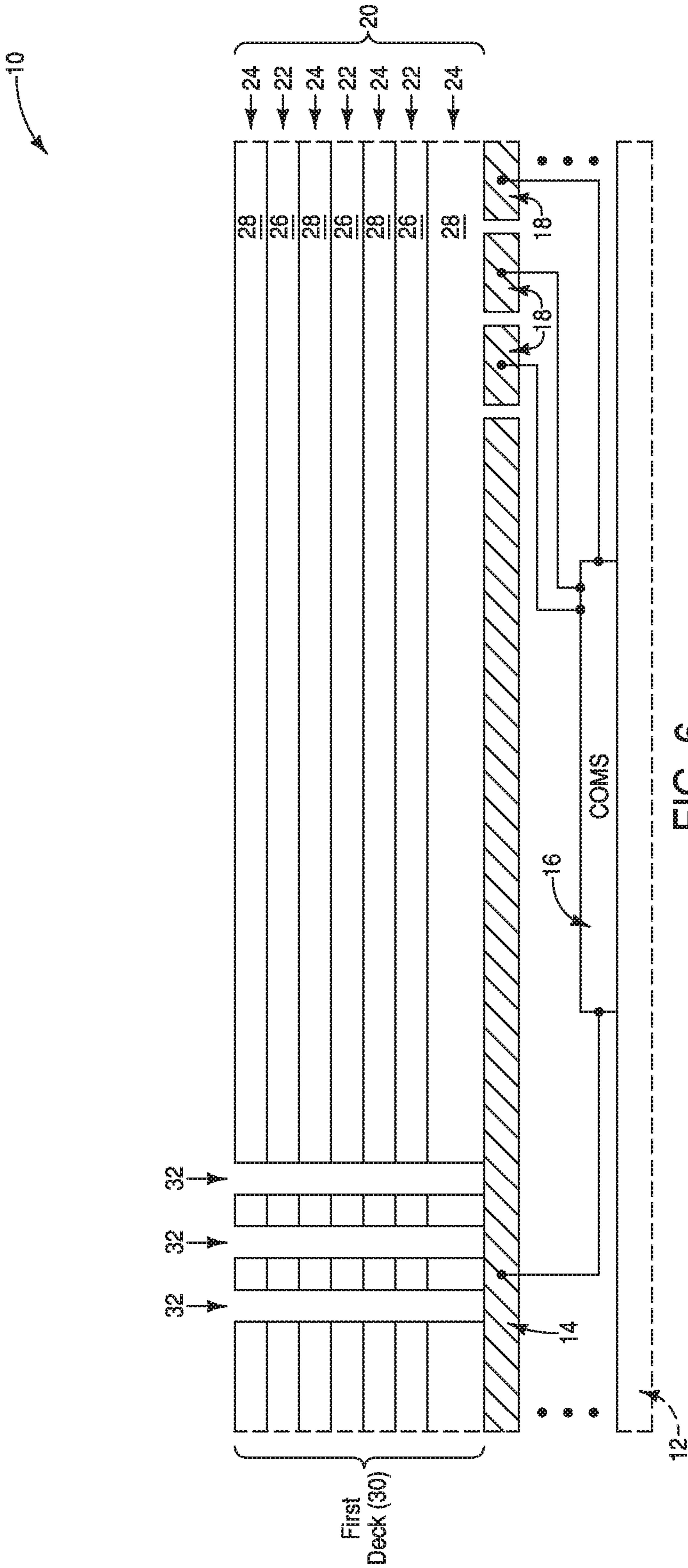
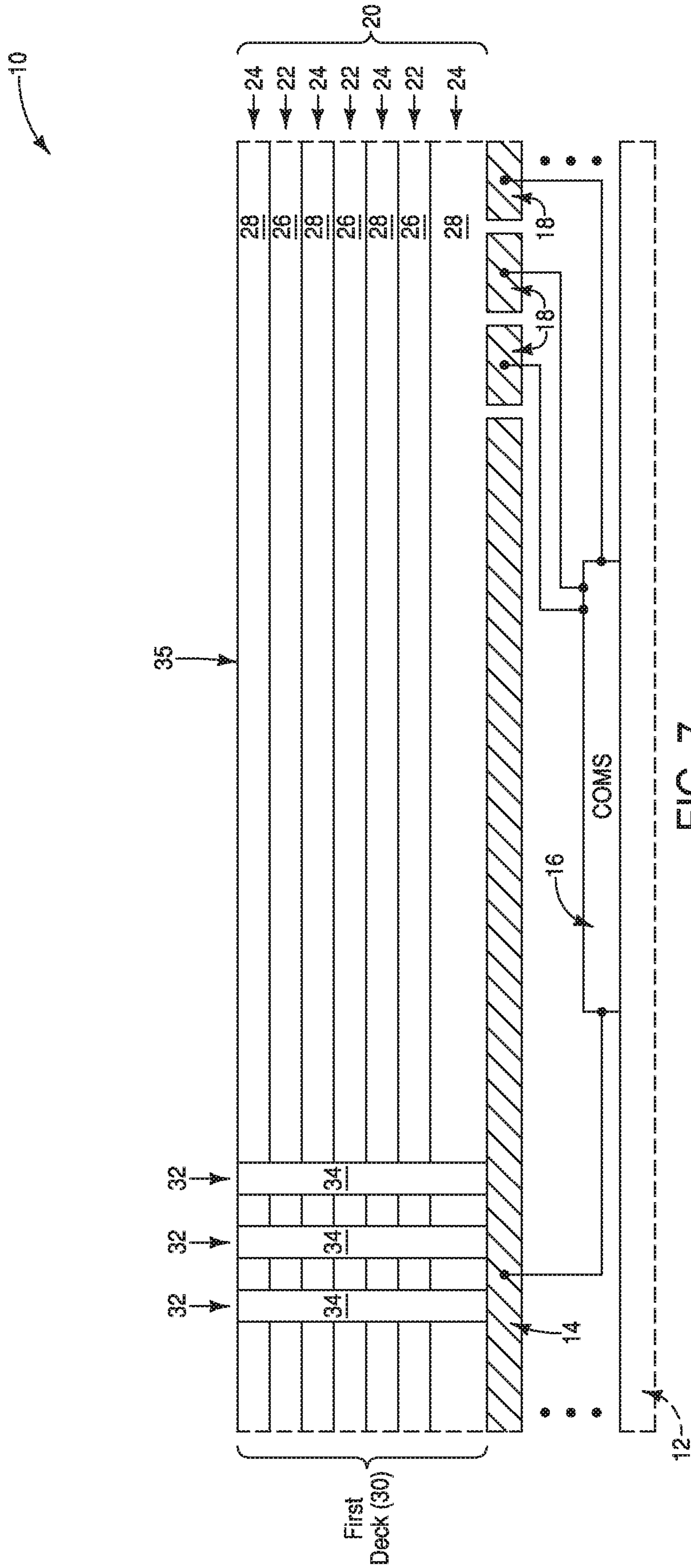


FIG. 6



10

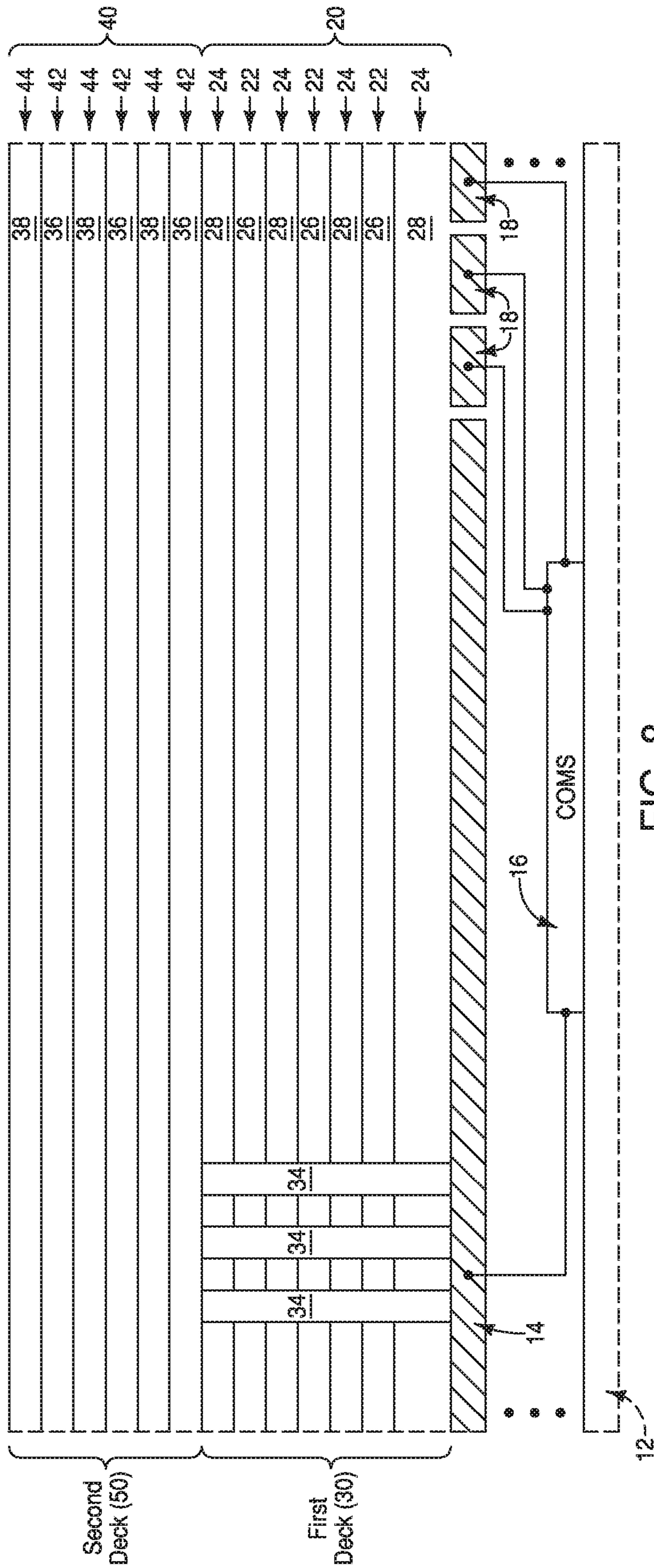


FIG. 8

10

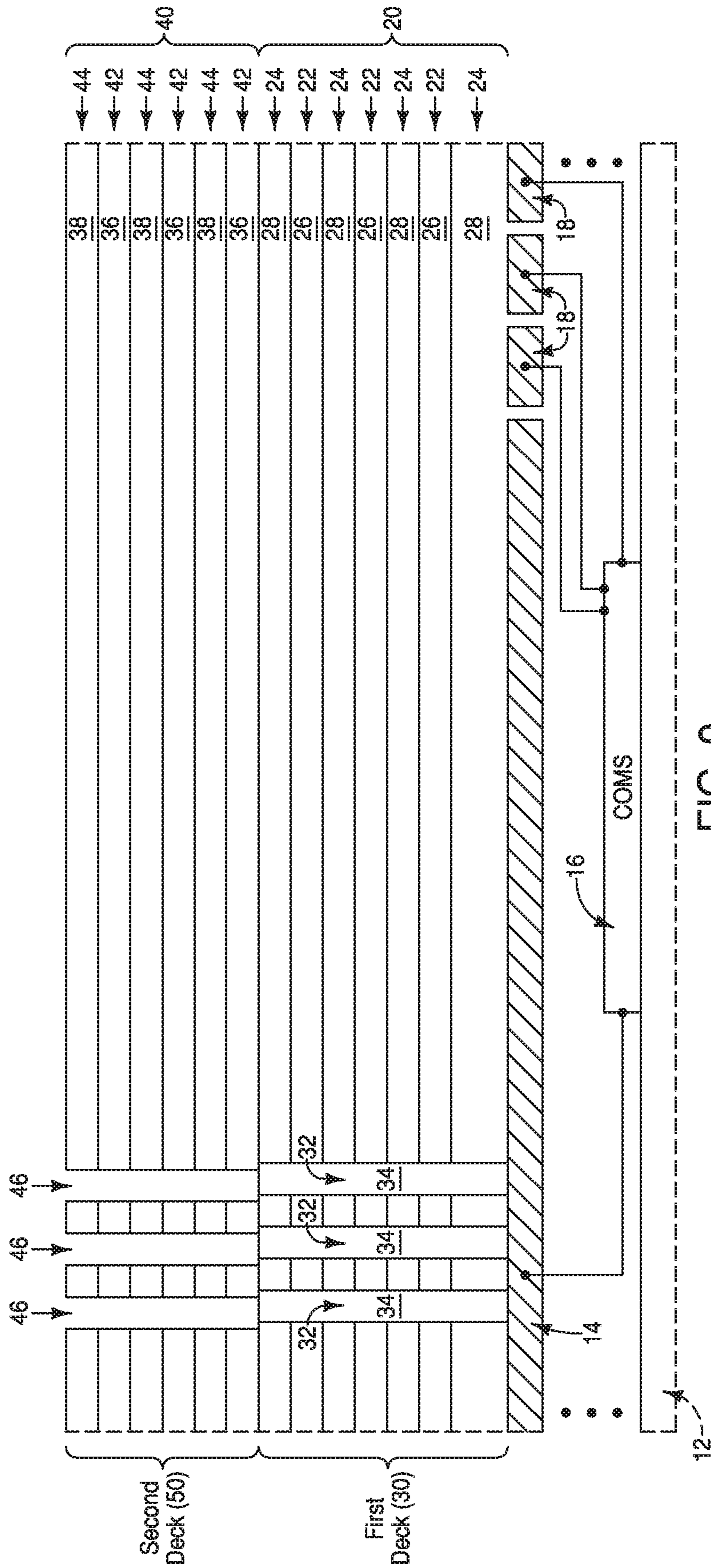


FIG. 9

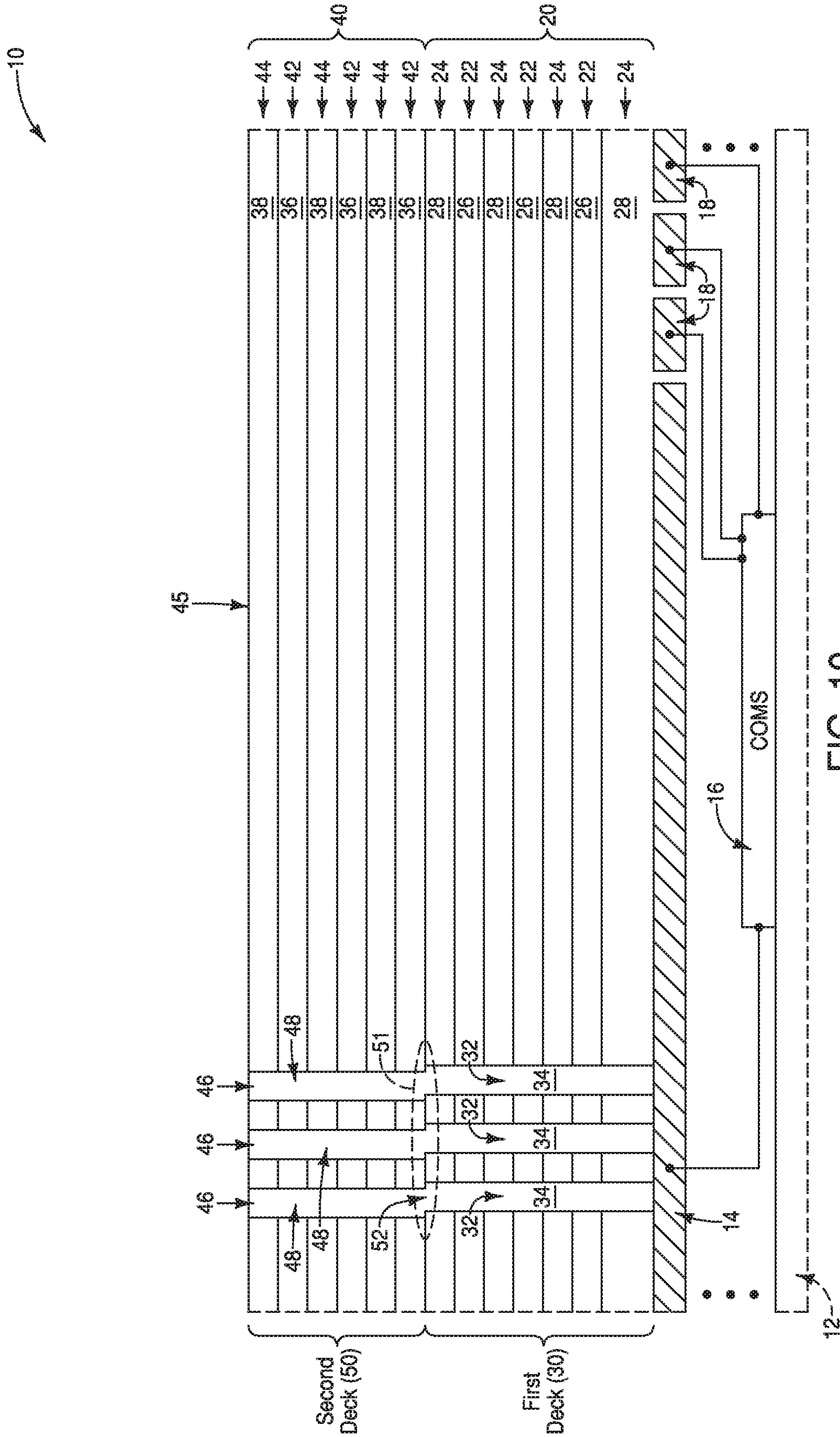


FIG. 10

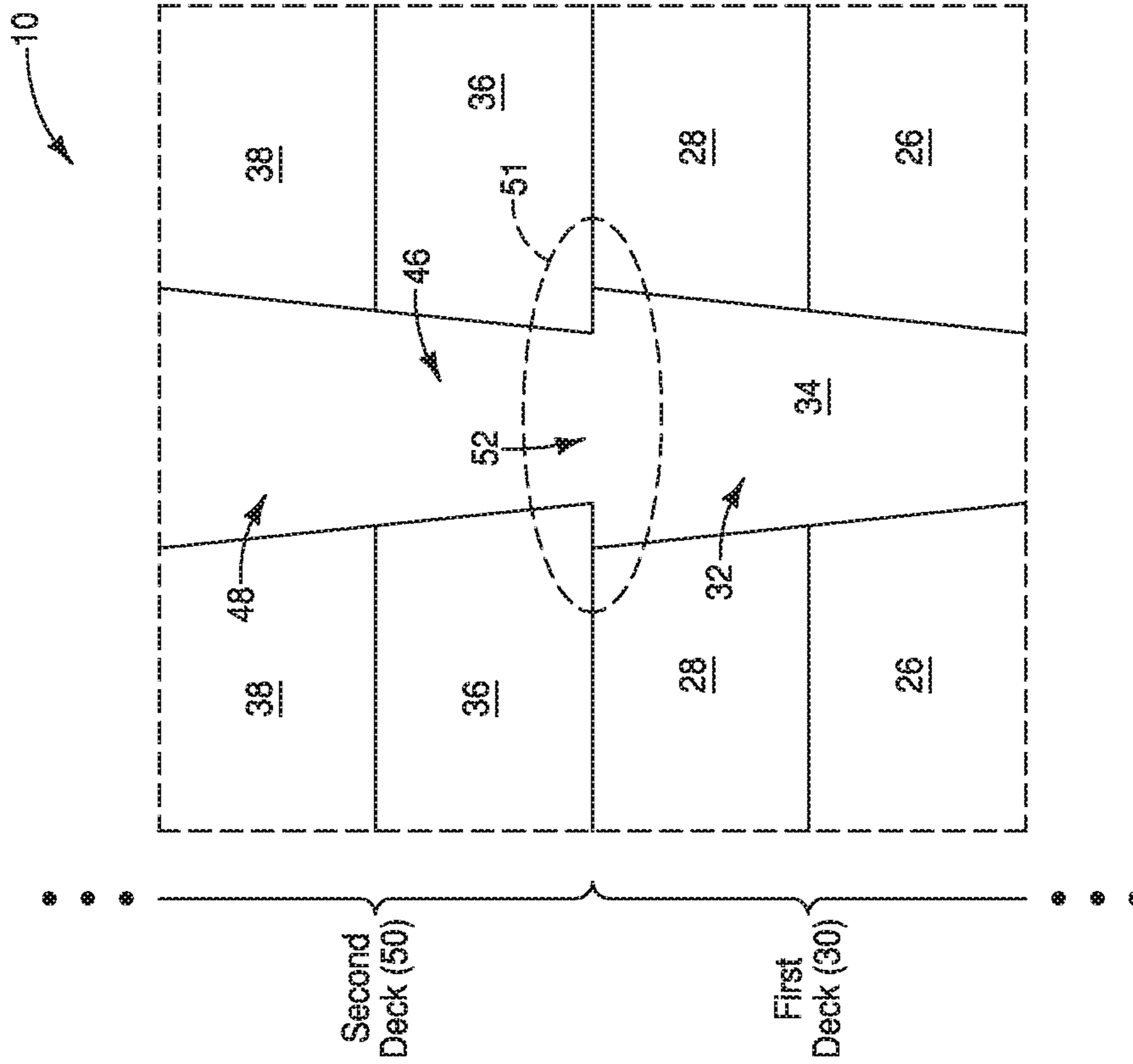


FIG. 10A

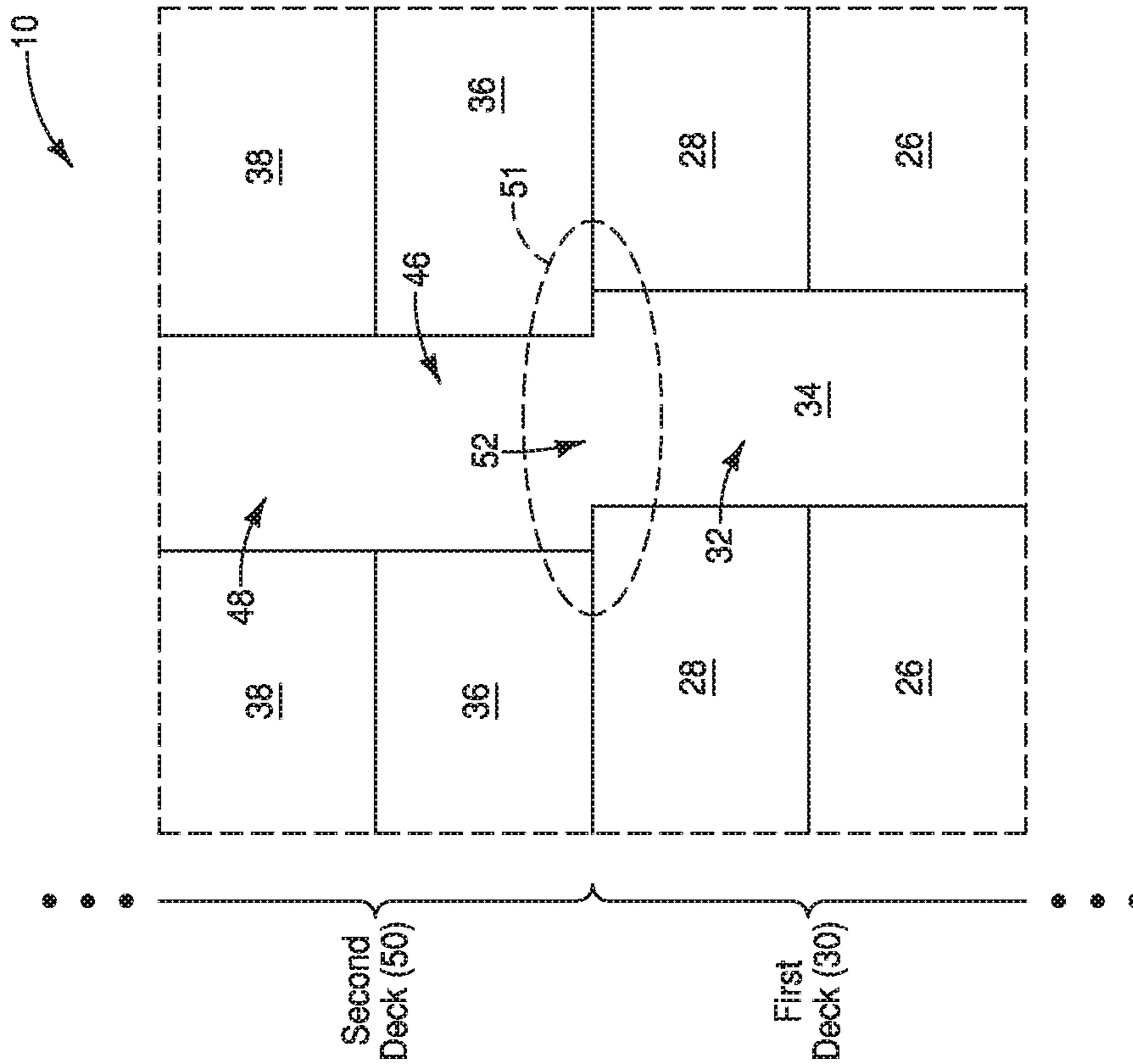


FIG. 10B

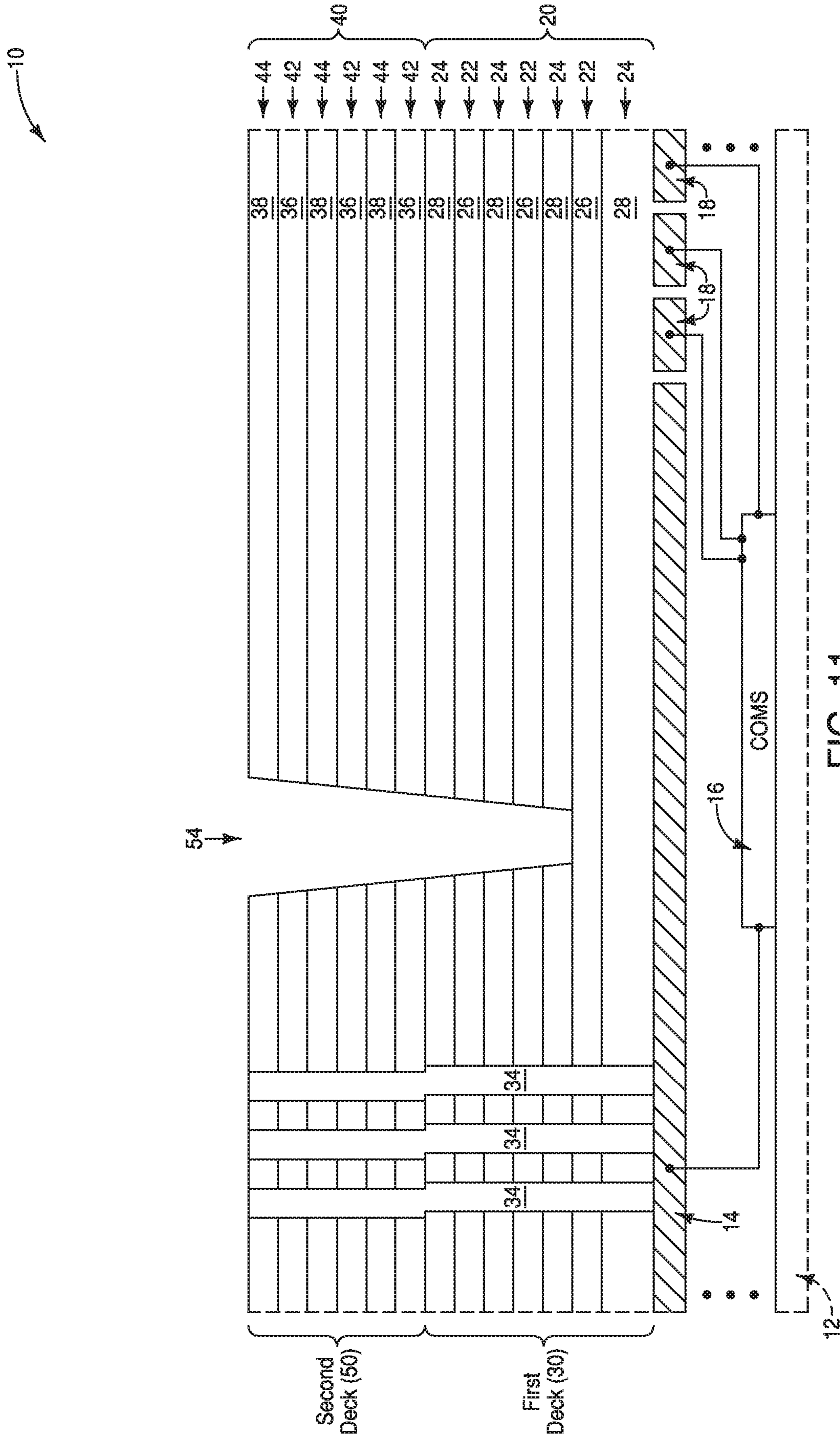


FIG. 11

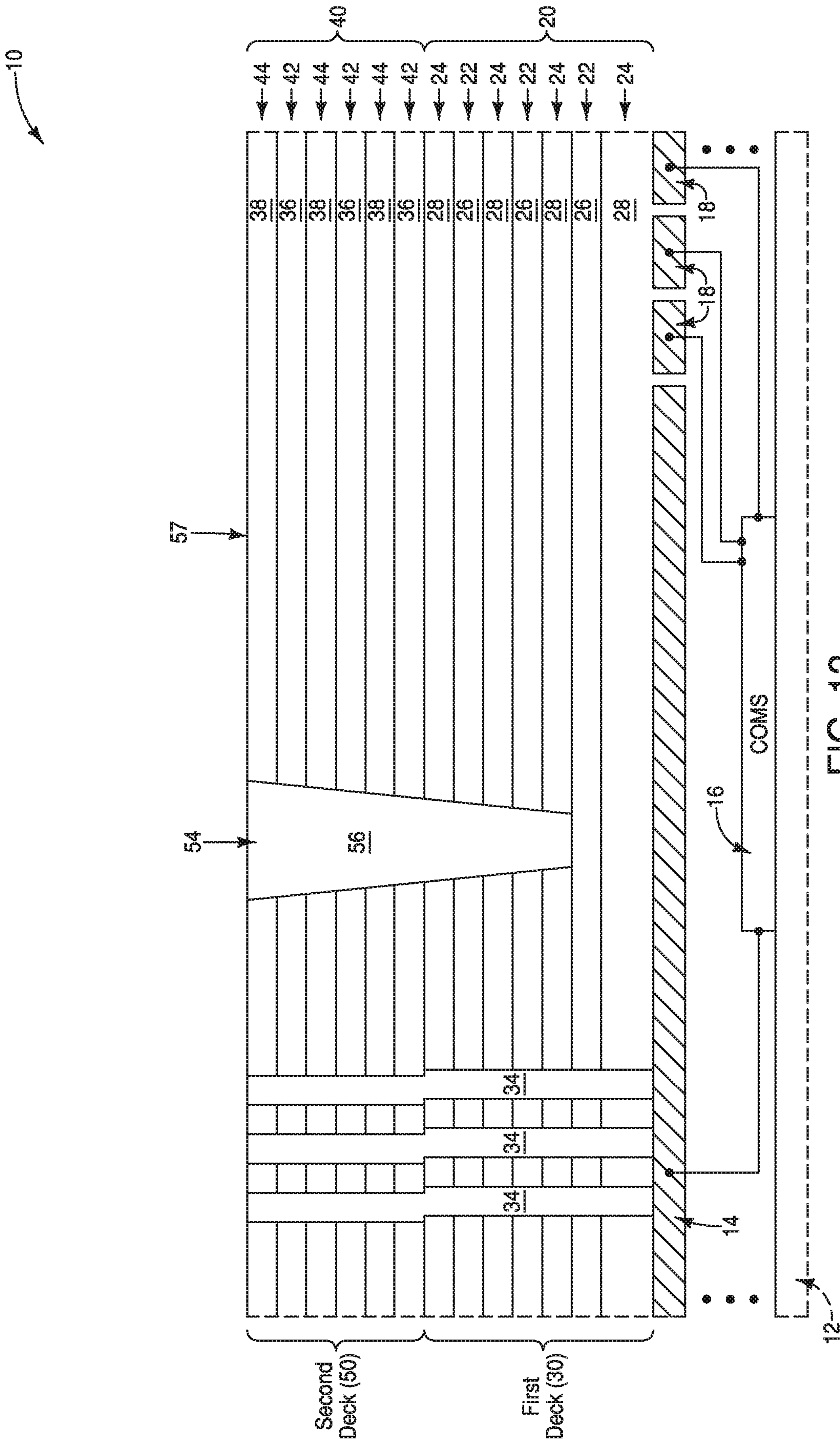


FIG. 12

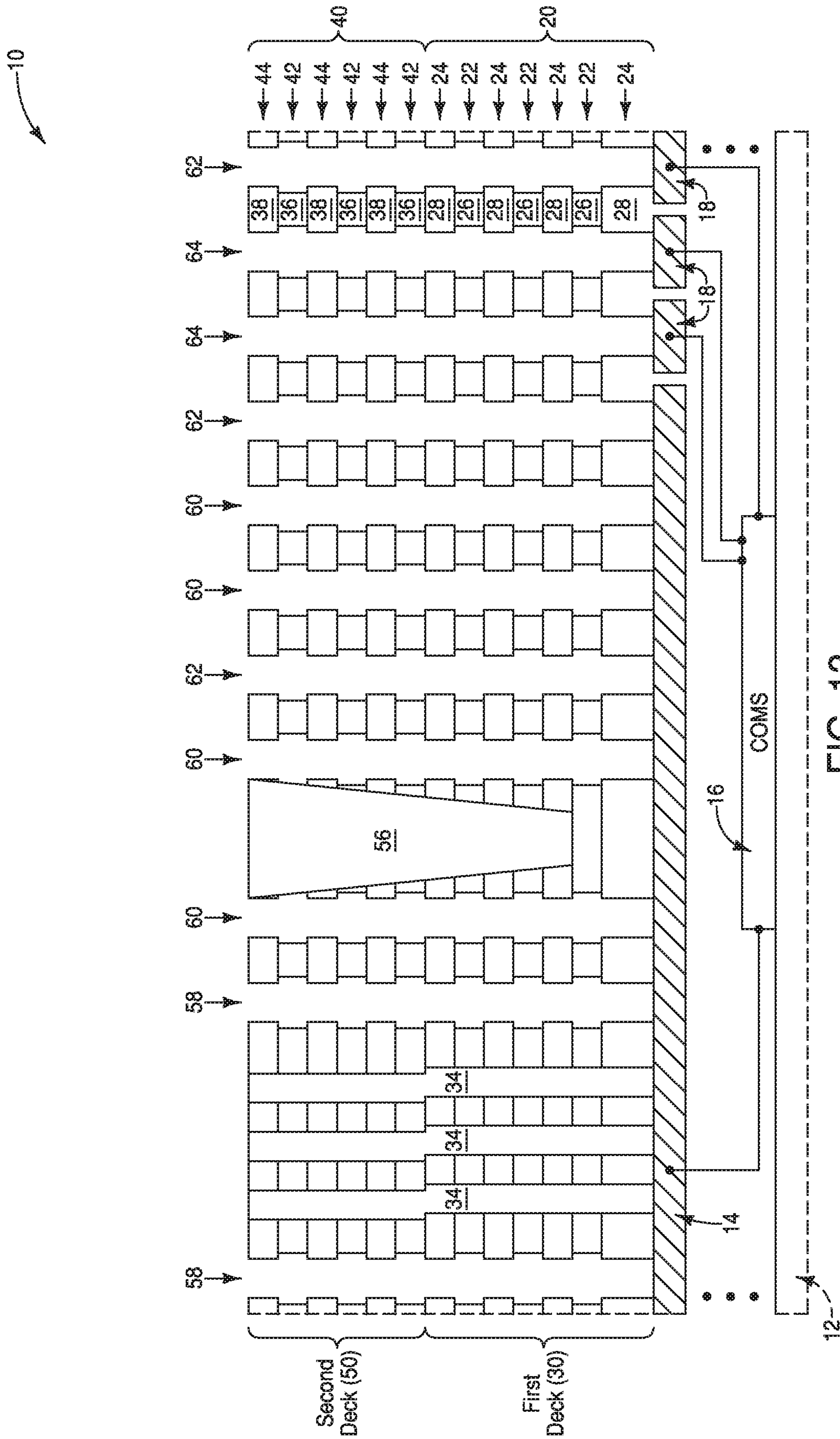


FIG. 13

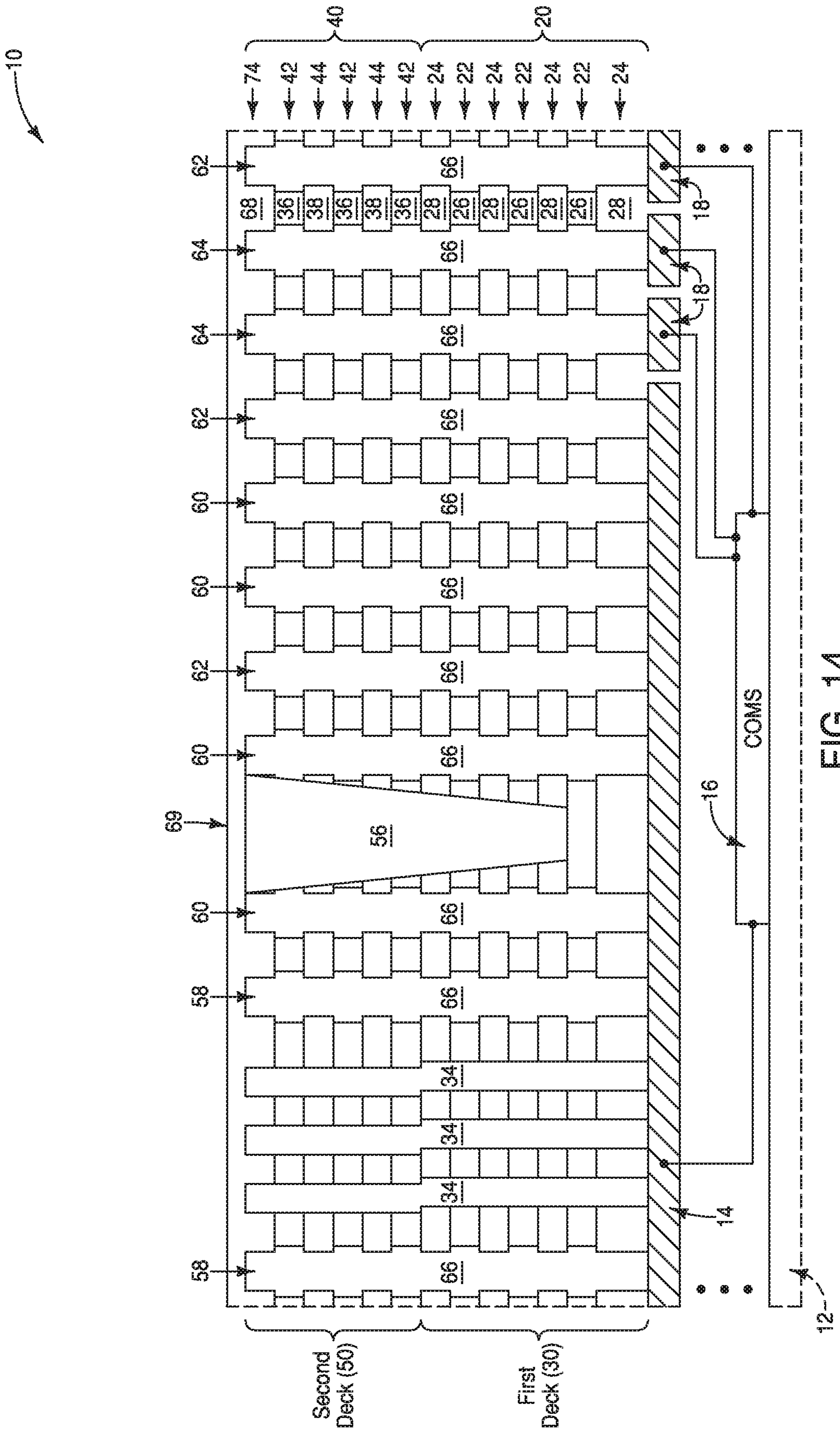


FIG. 14

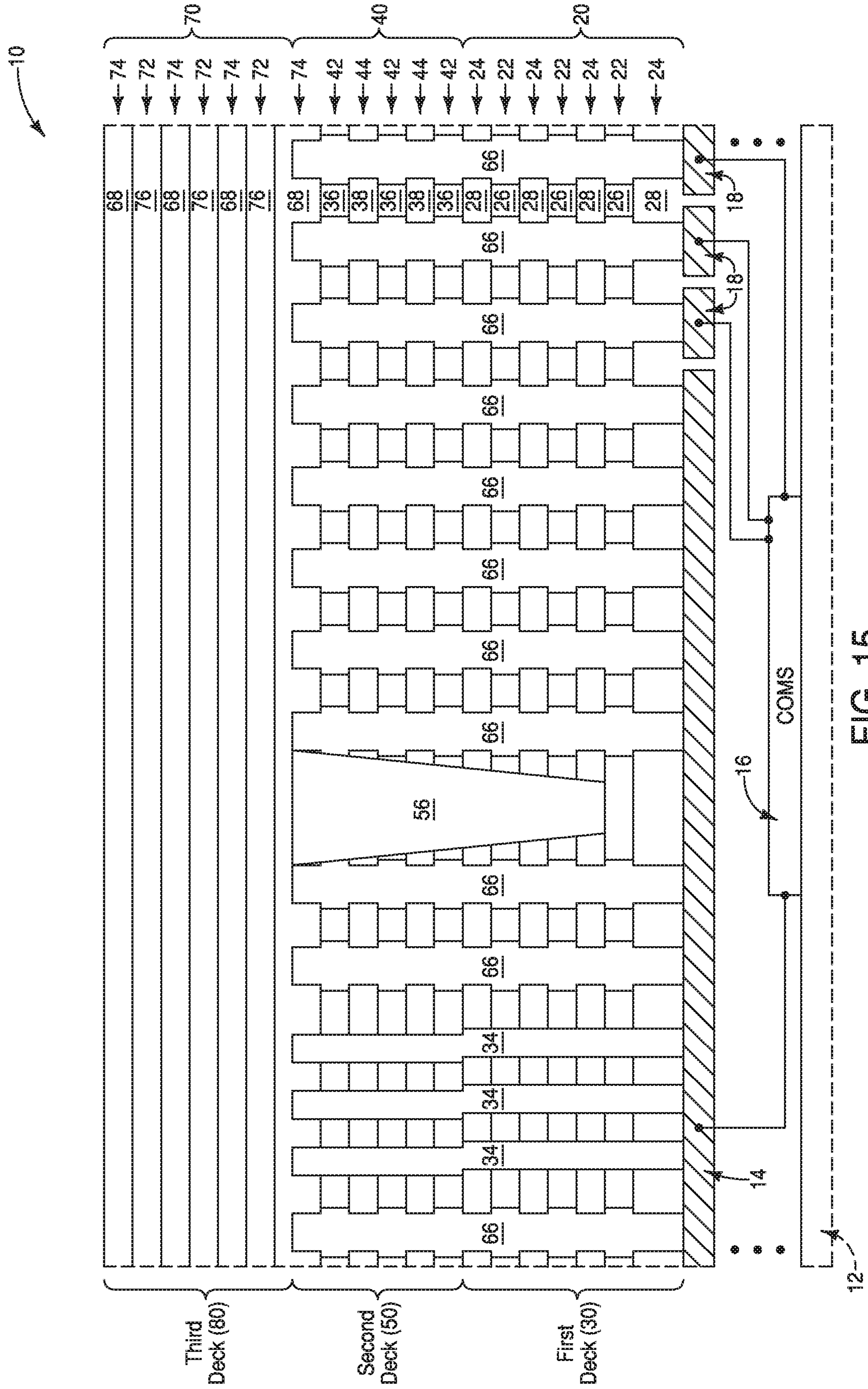


FIG. 15

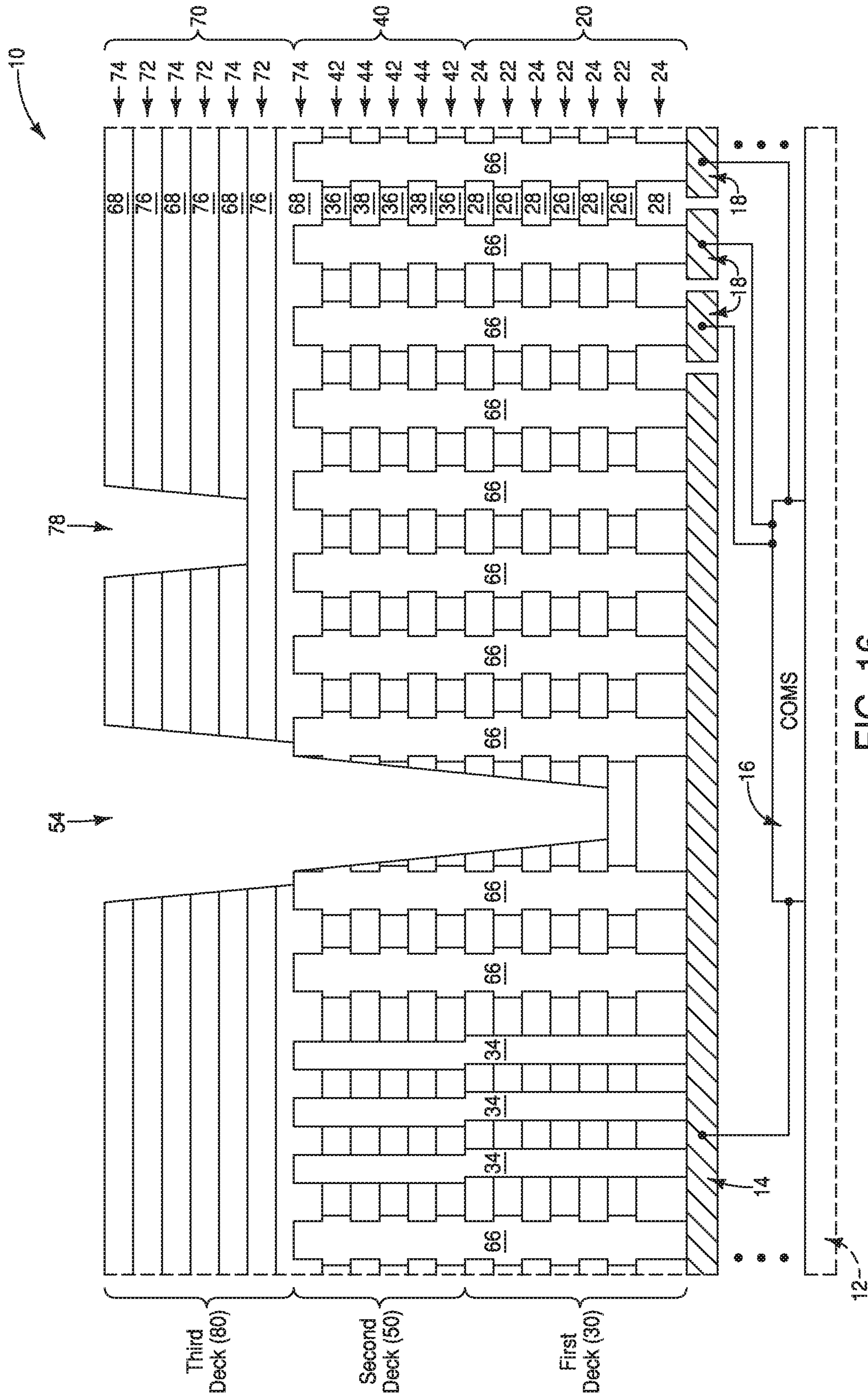


FIG. 16

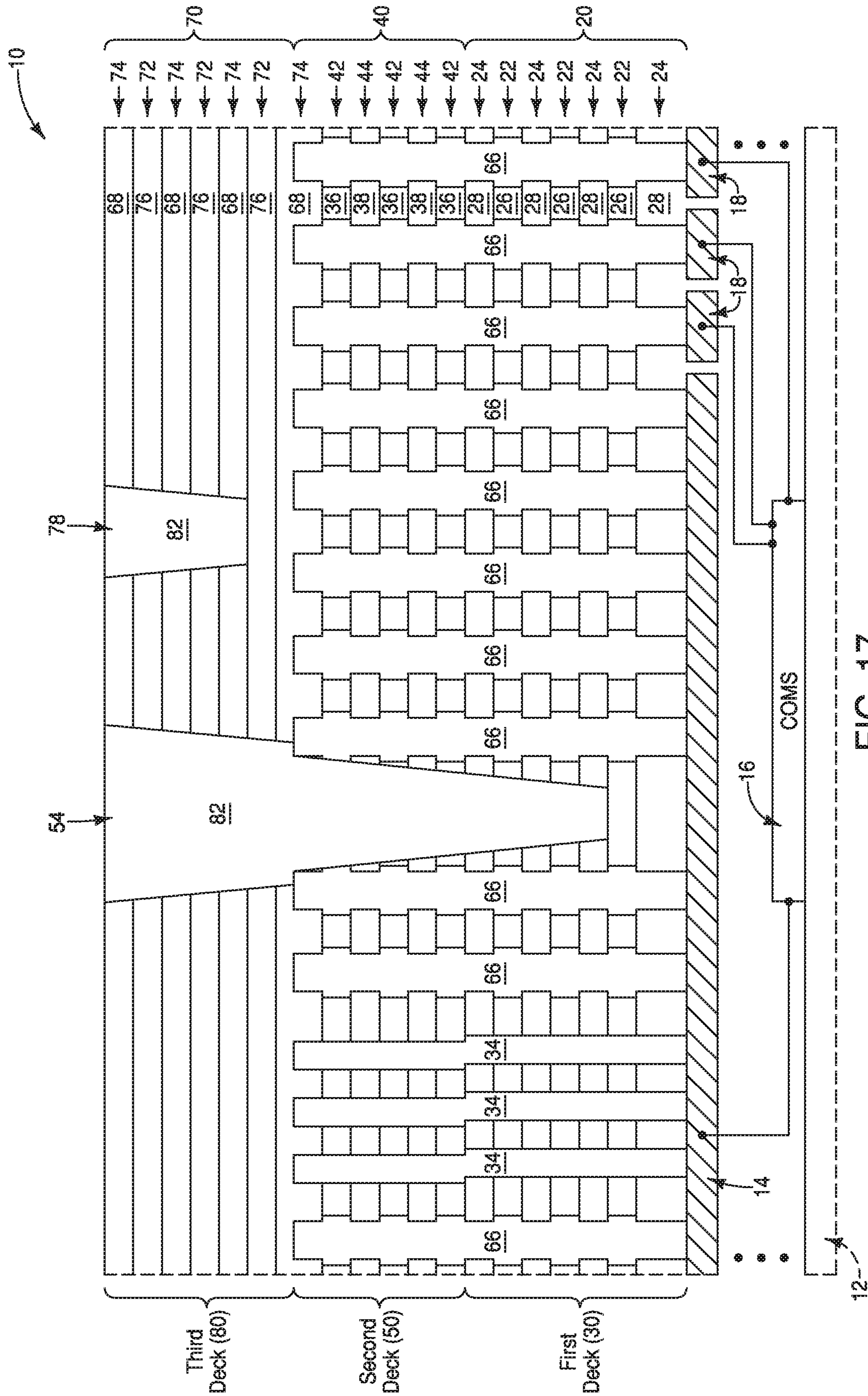


FIG. 17

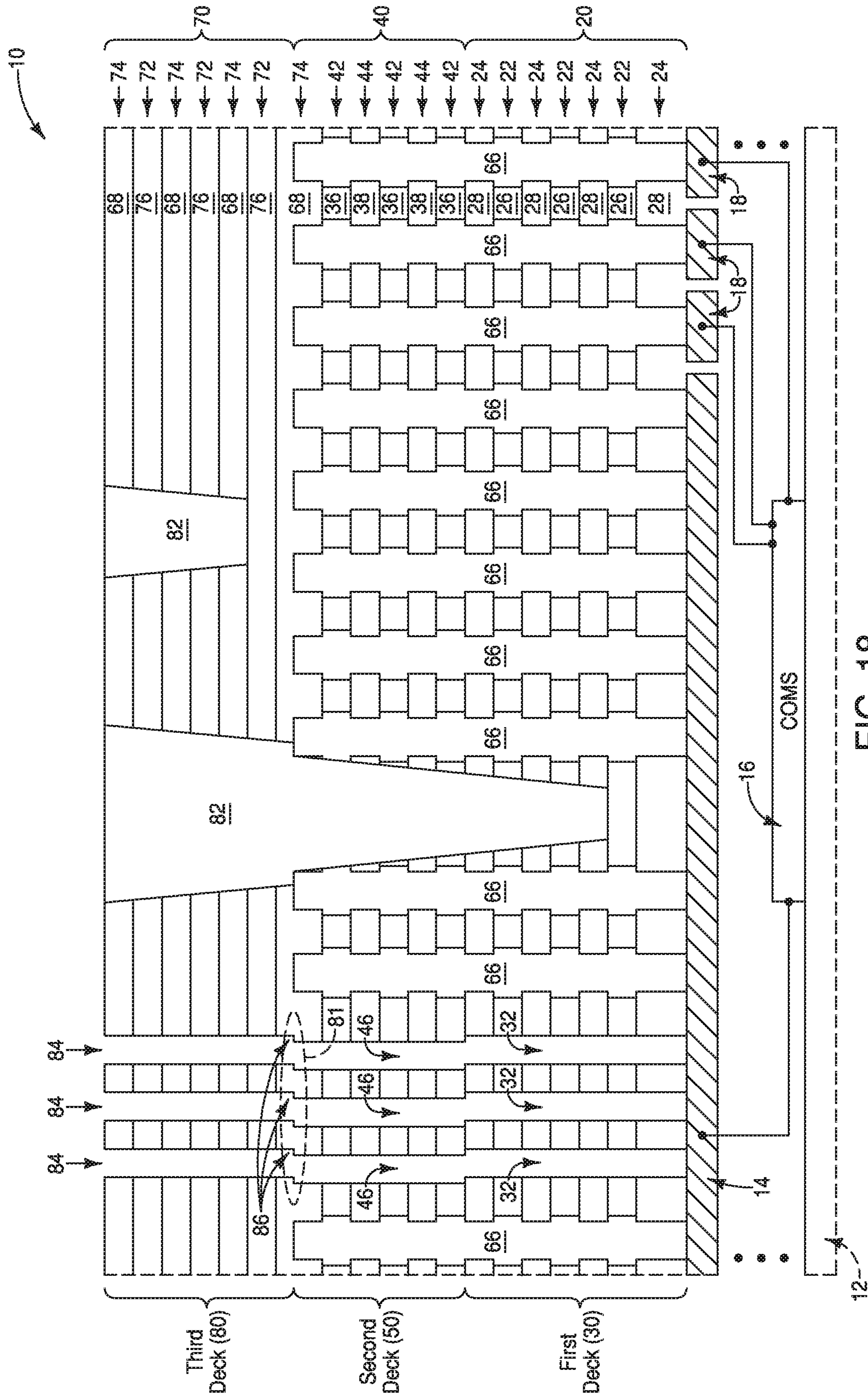


FIG. 18

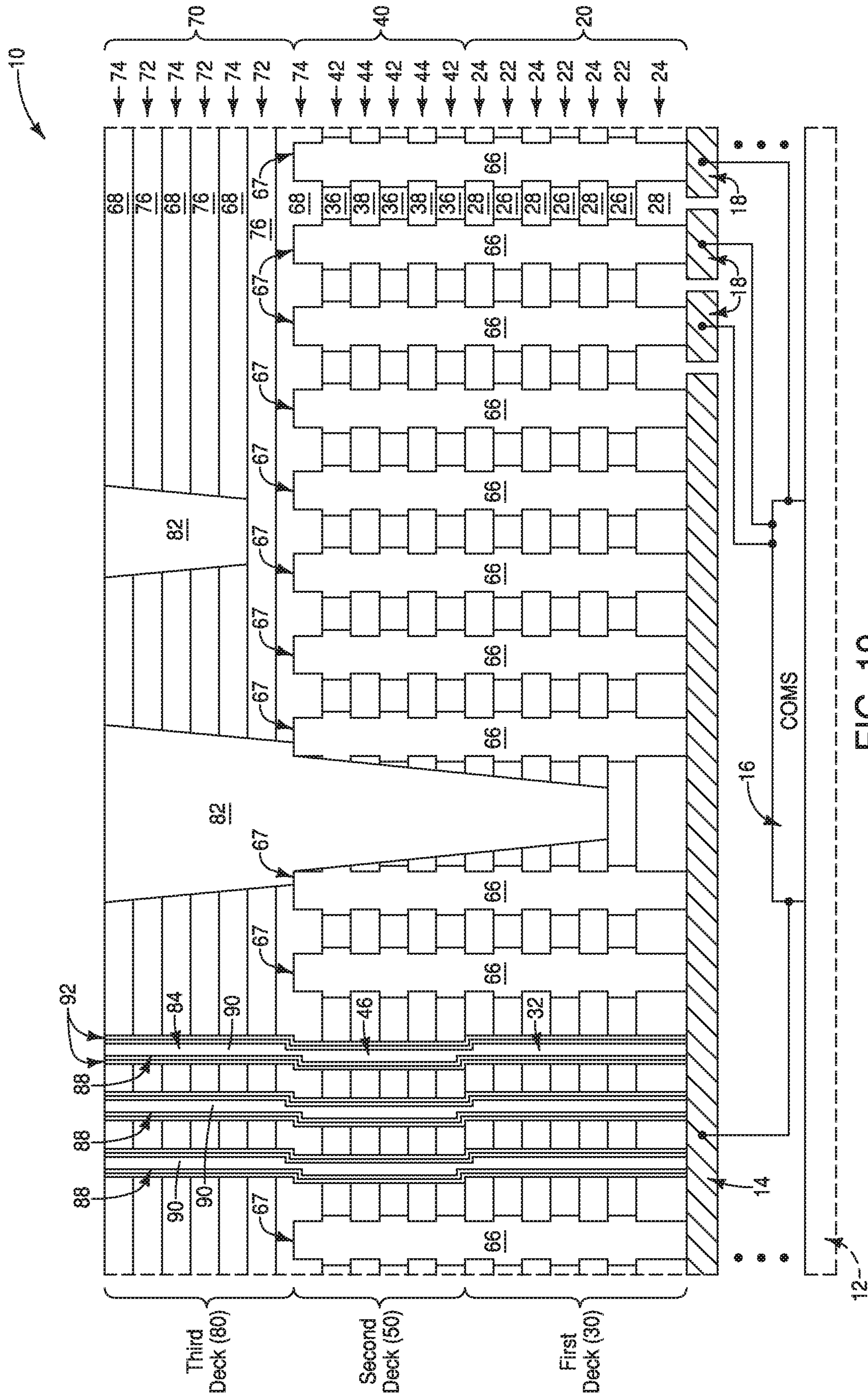


FIG. 19

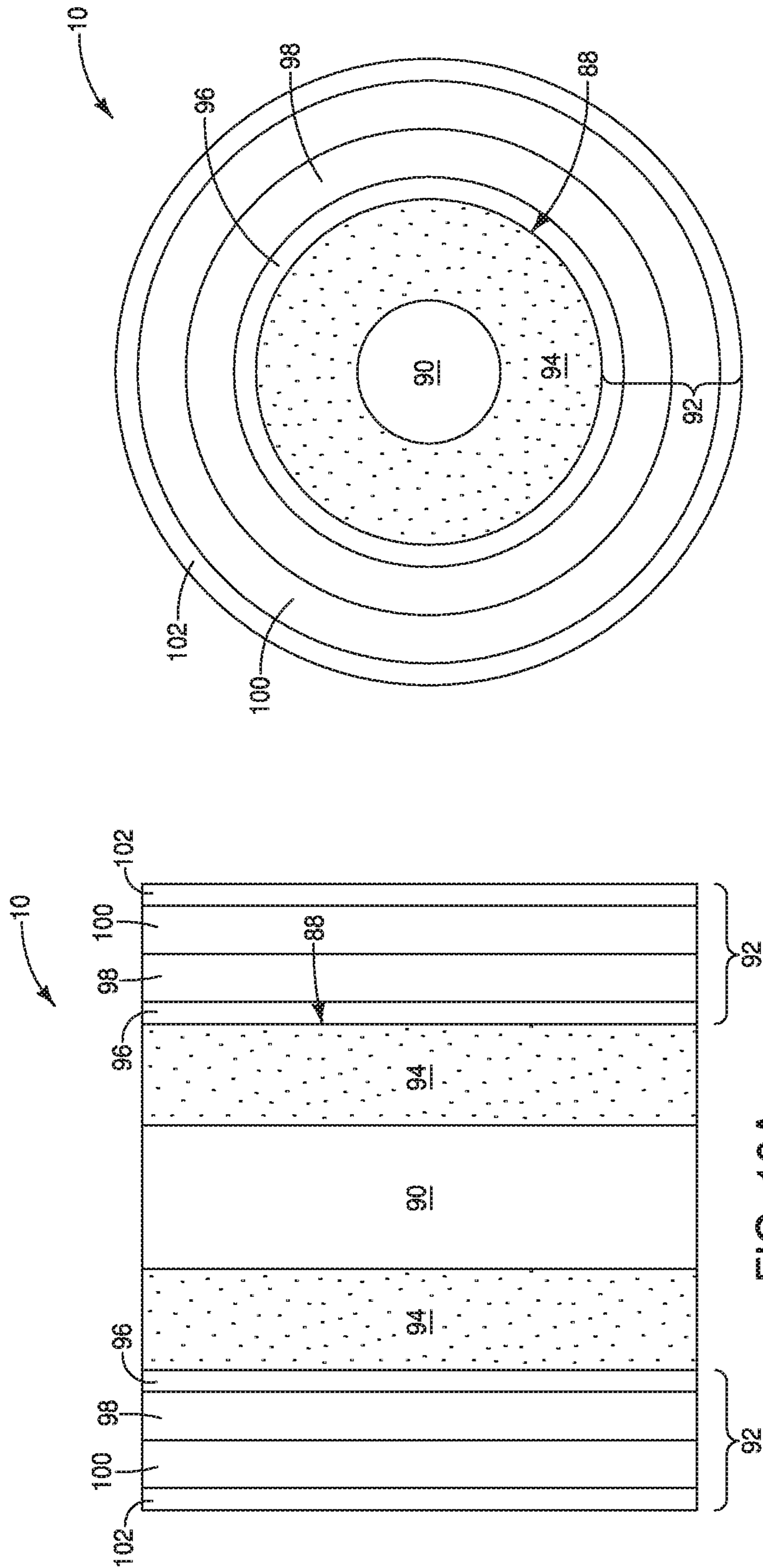


FIG. 19B

FIG. 19A

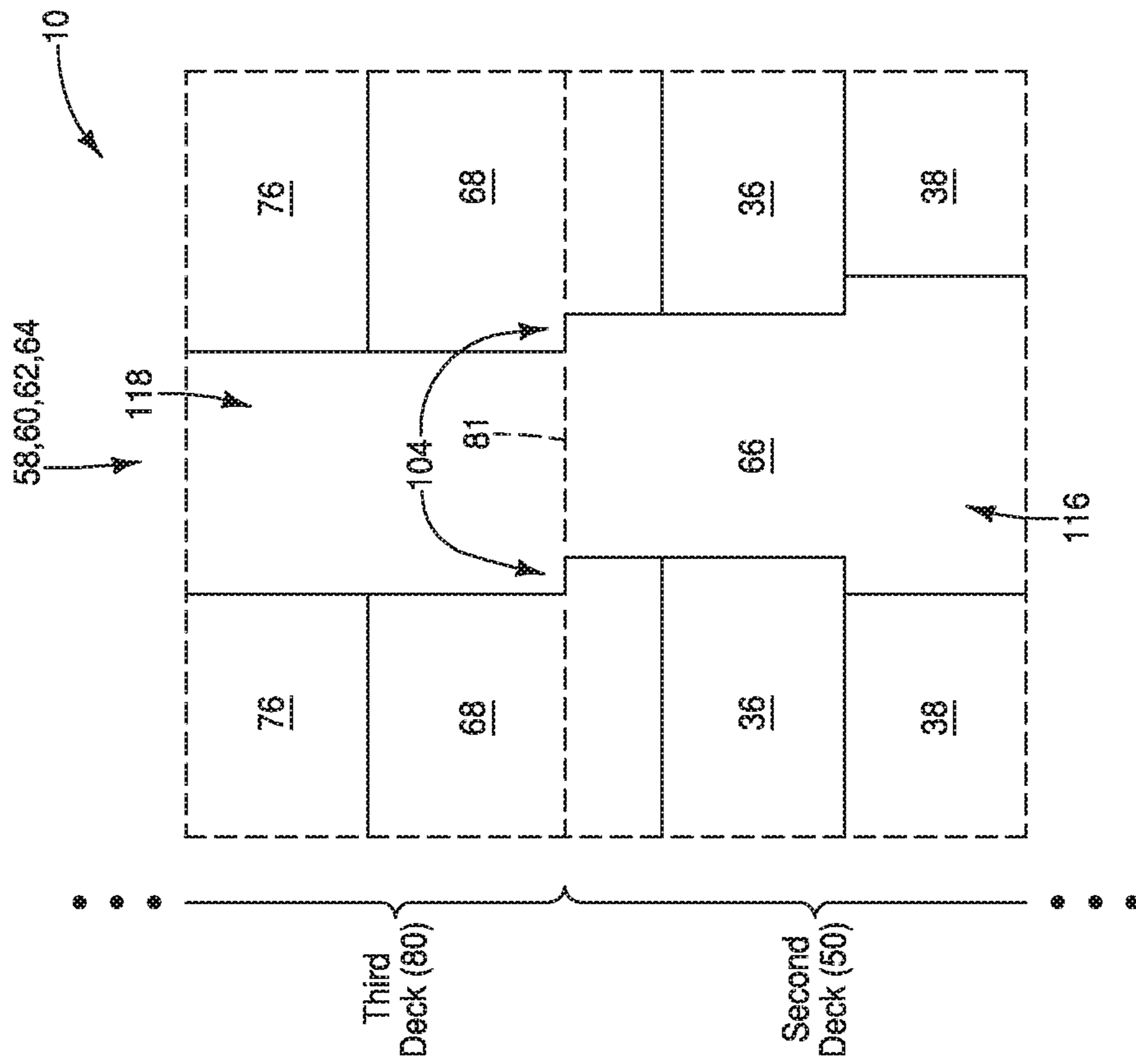


FIG. 20A

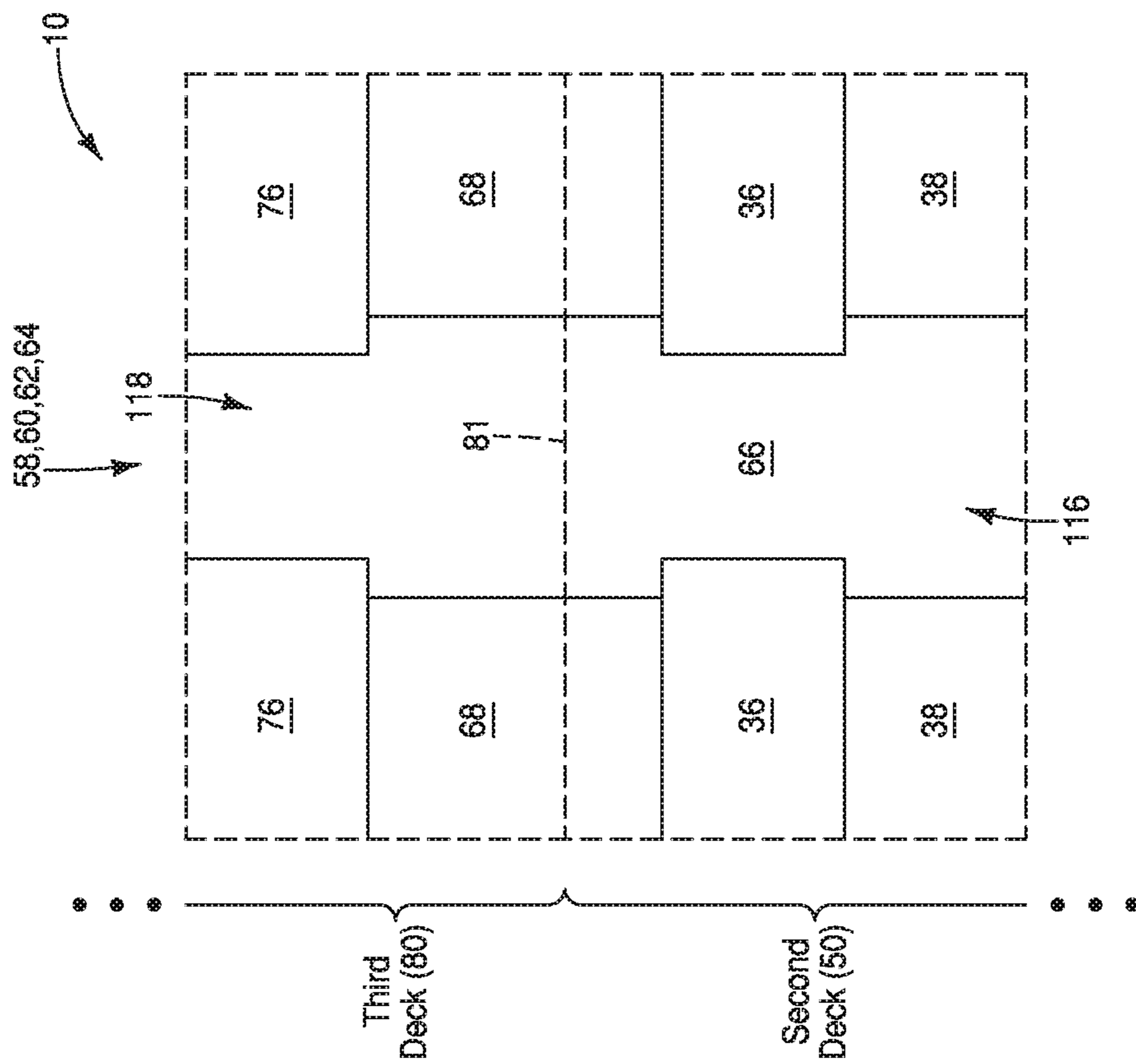


FIG. 20B

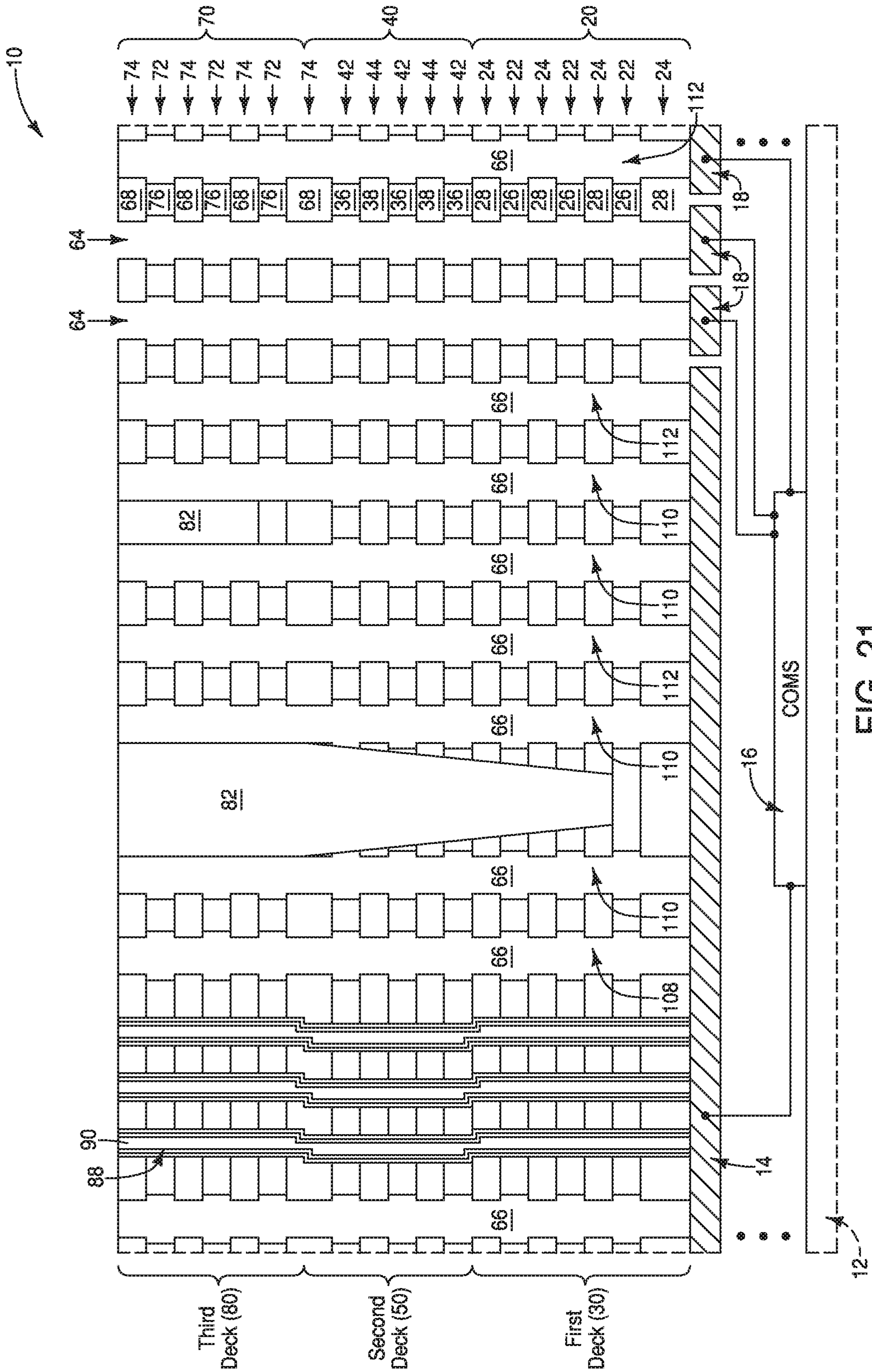


FIG. 21

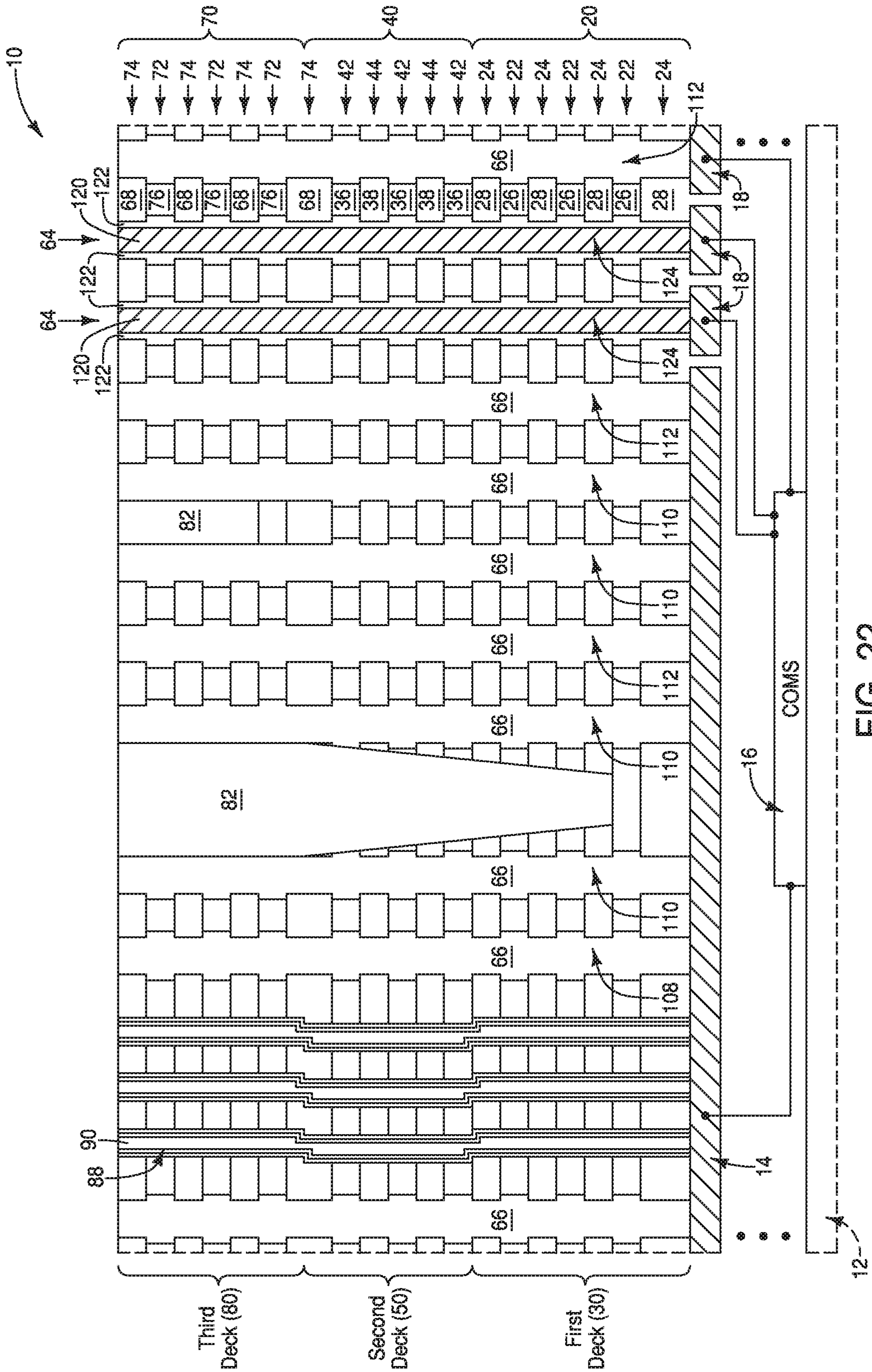


FIG. 22

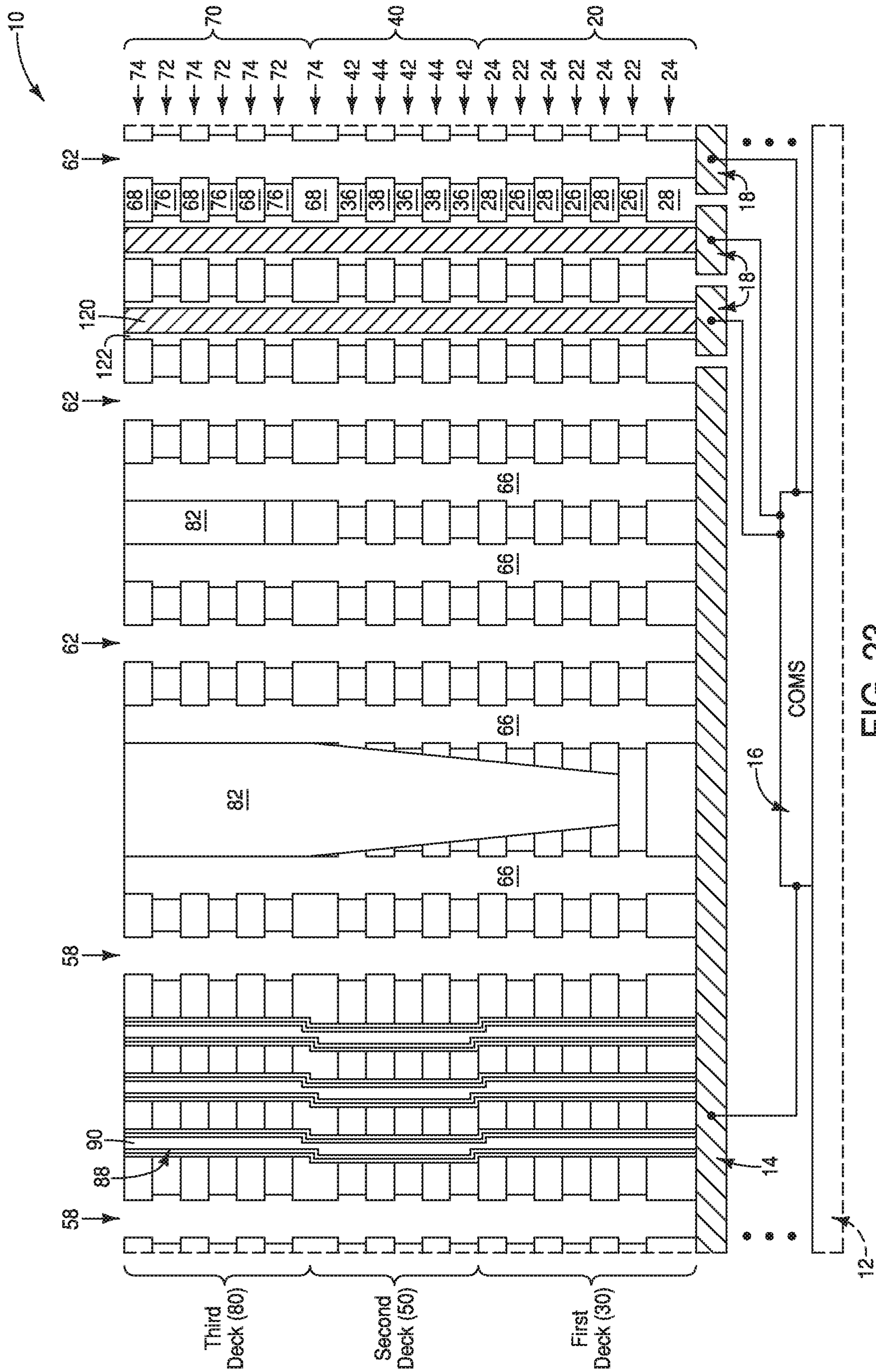


FIG. 23

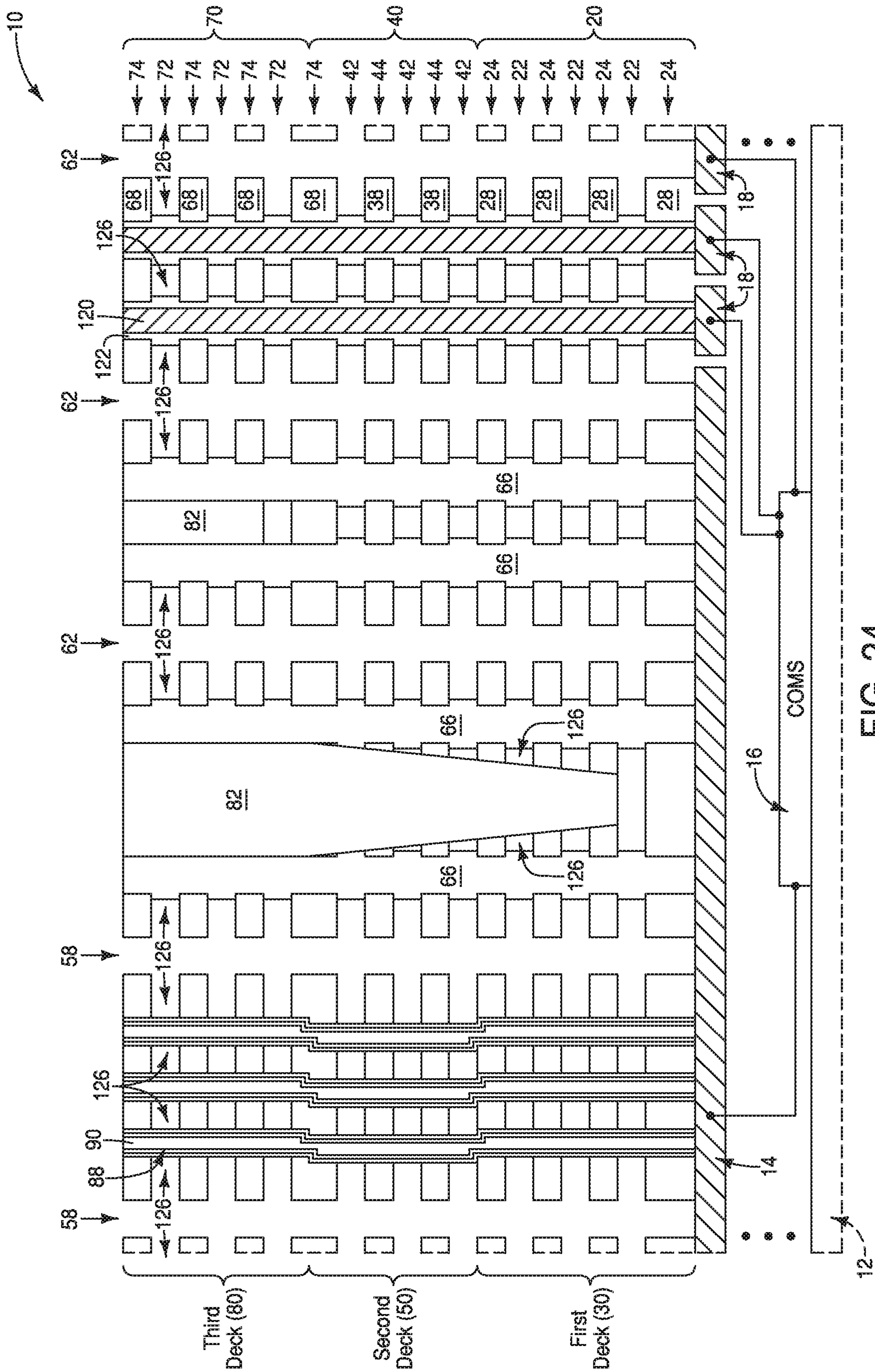


FIG. 24

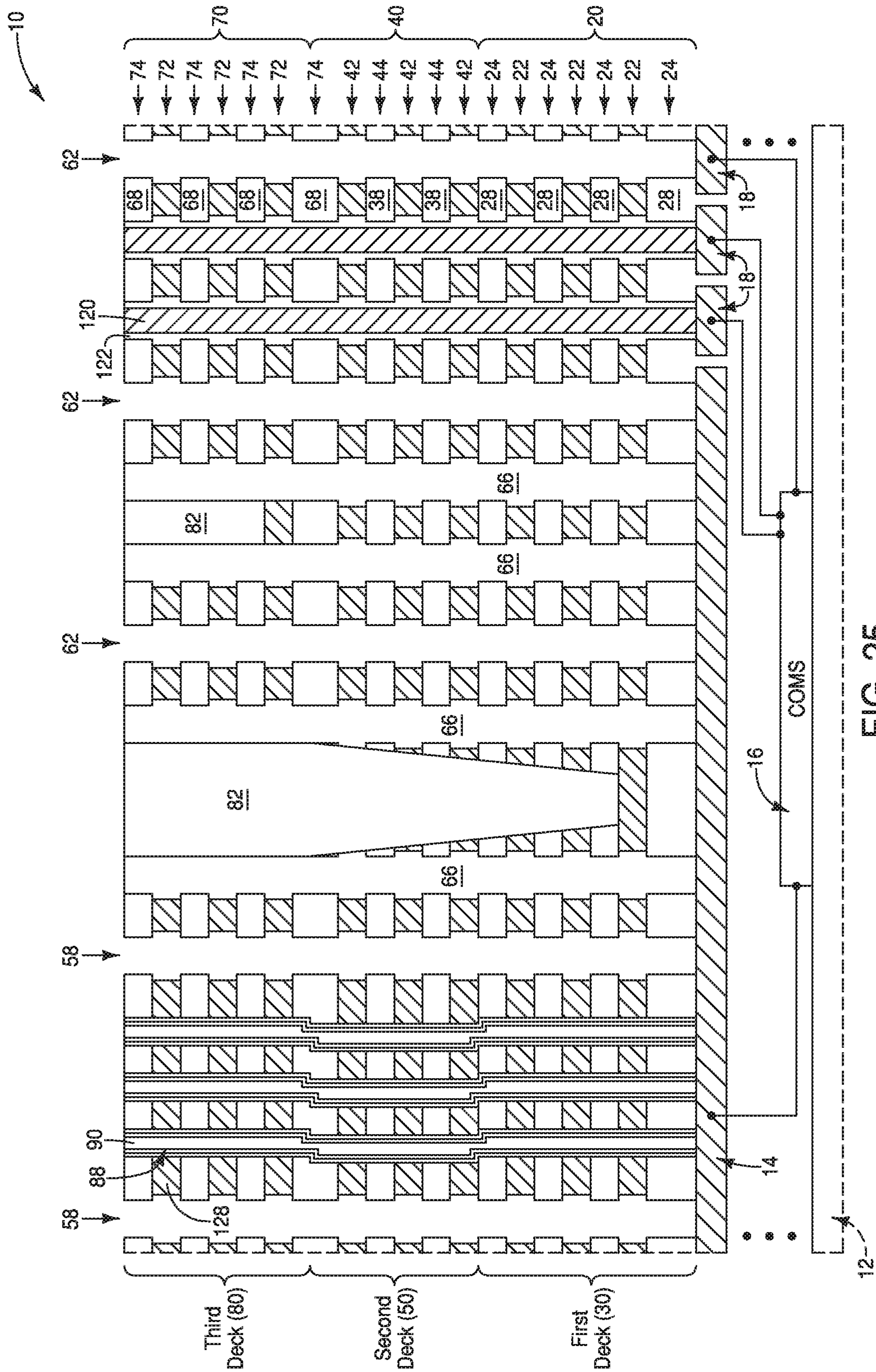


FIG. 25

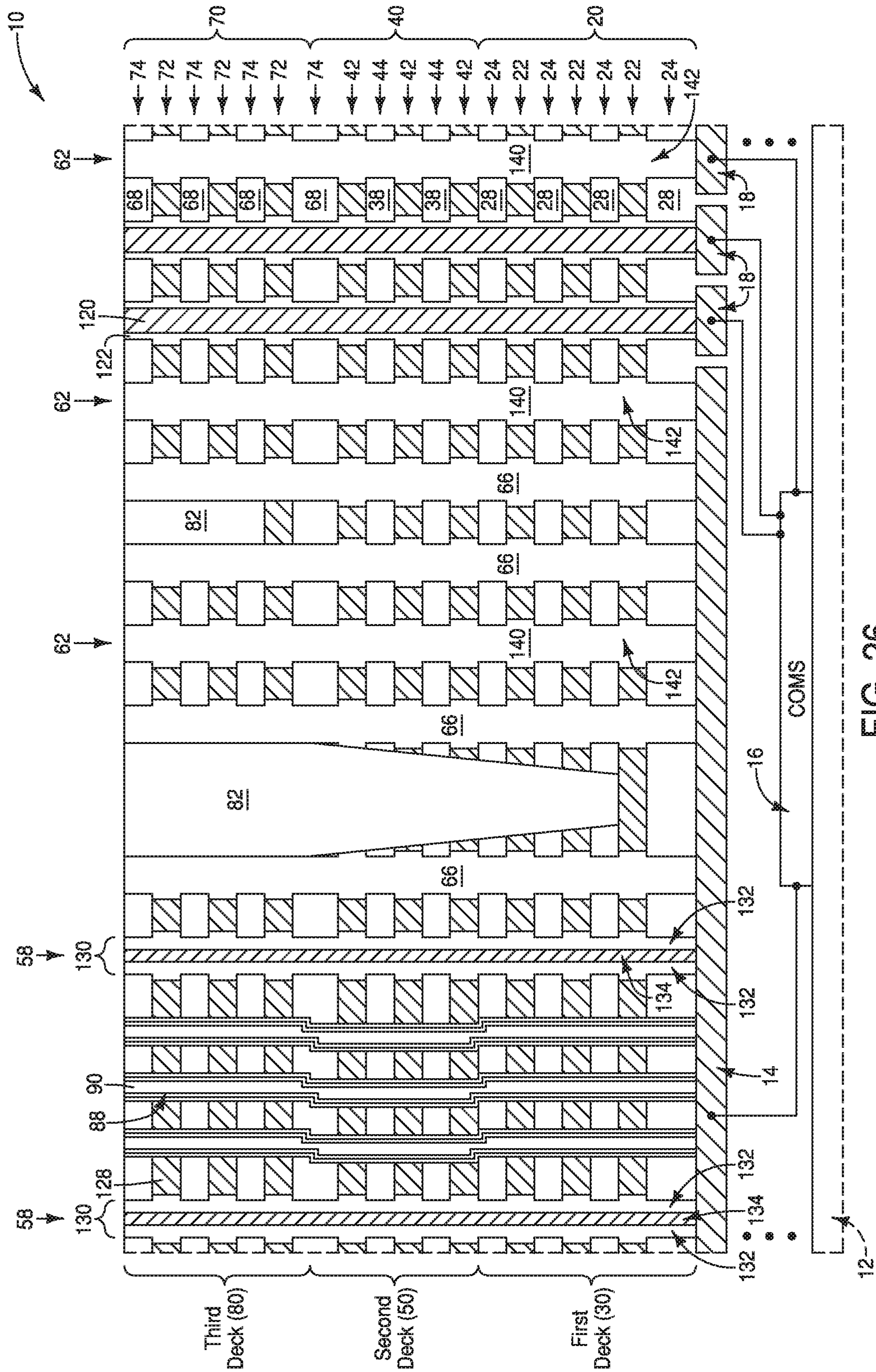


FIG. 26

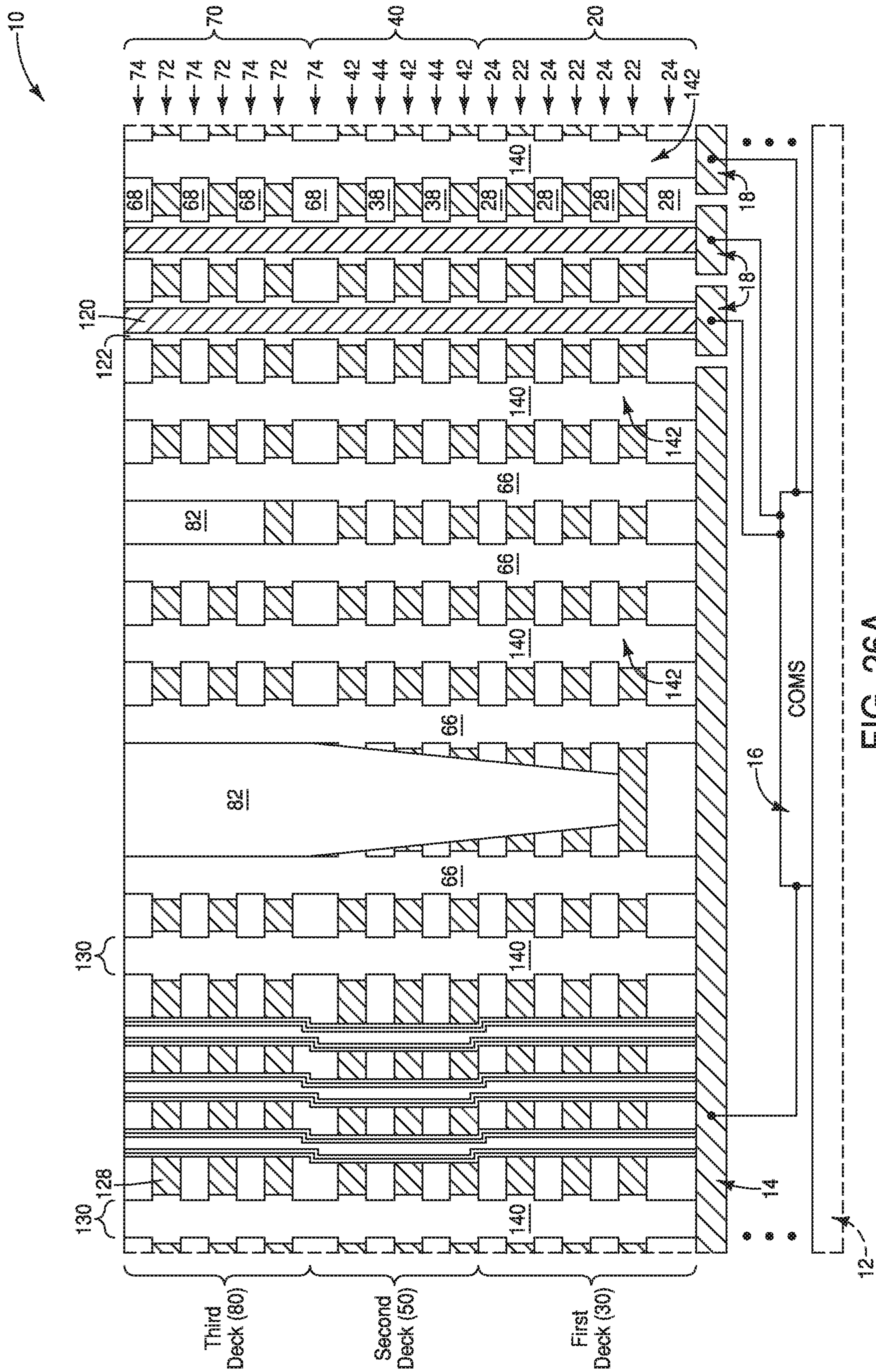


FIG. 26A

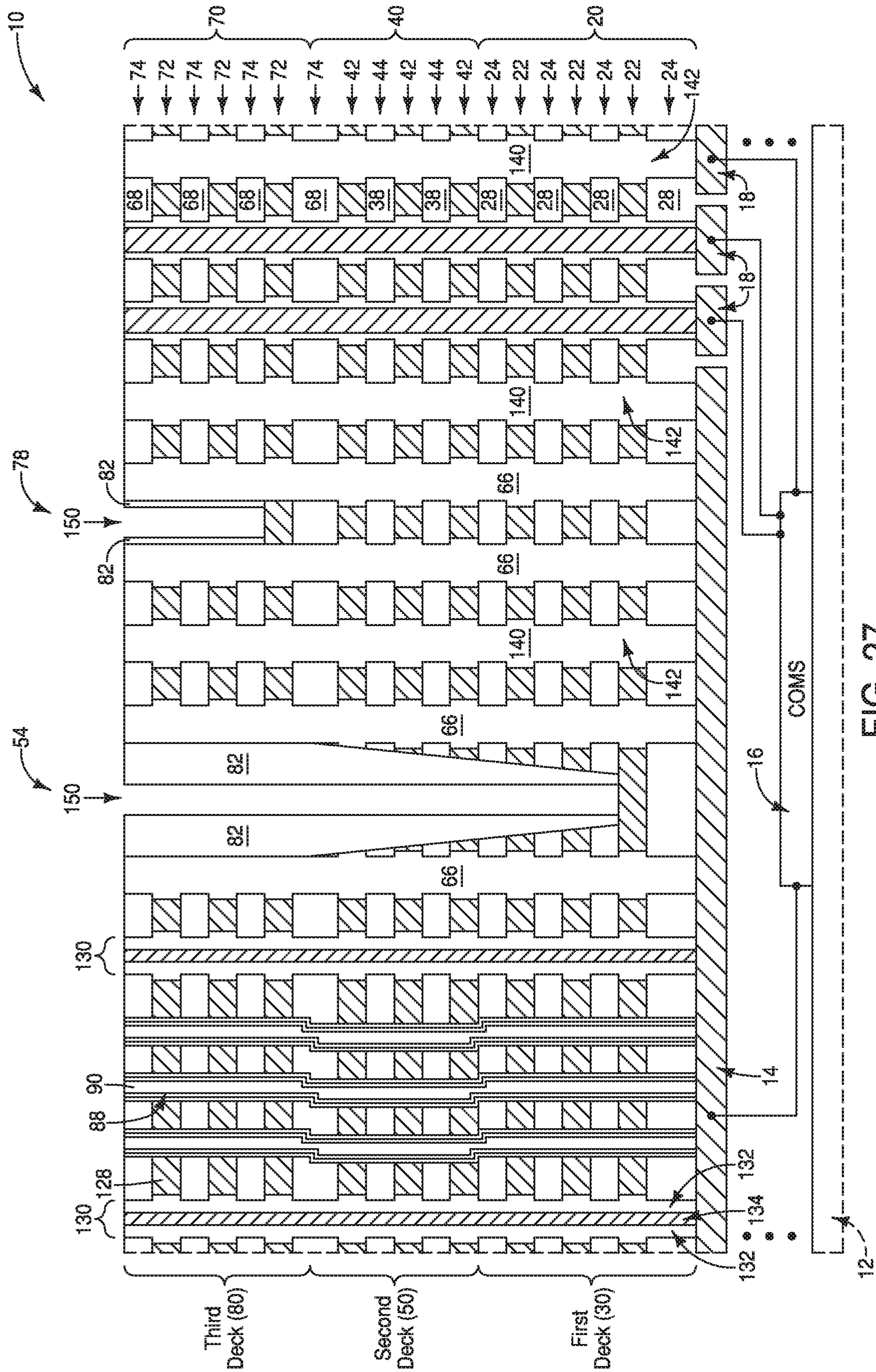


FIG. 27

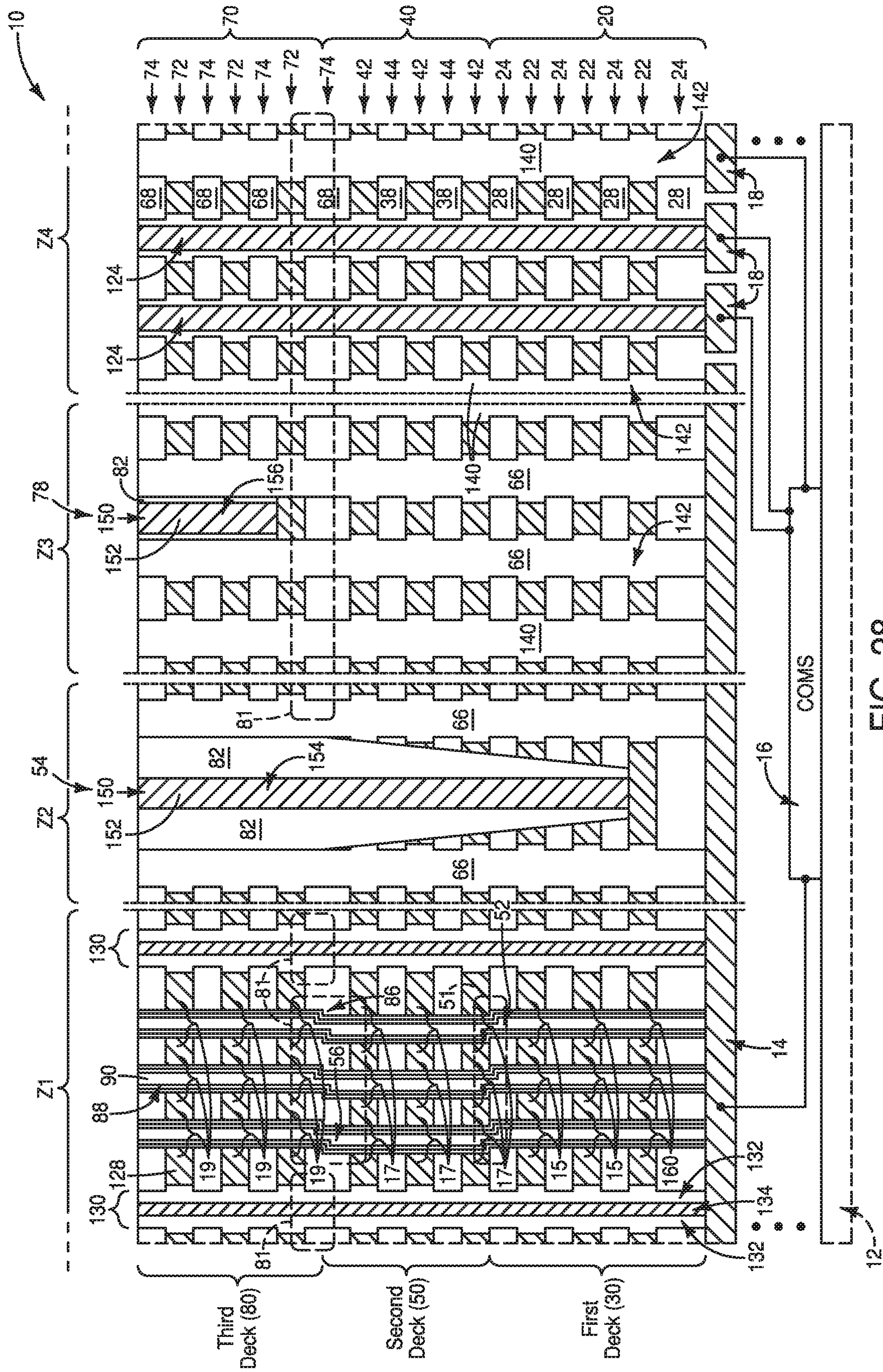


FIG. 28

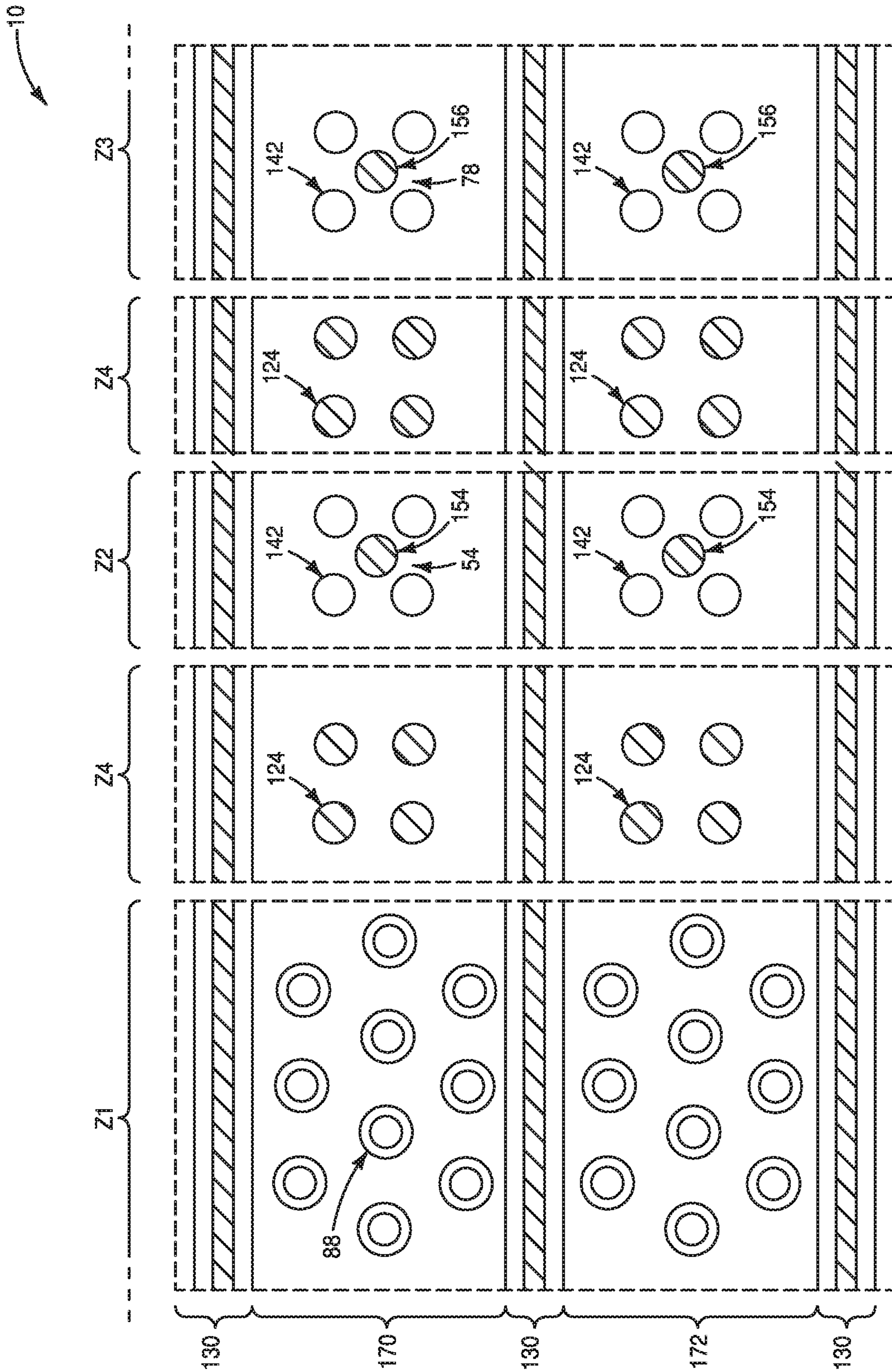


FIG. 28A

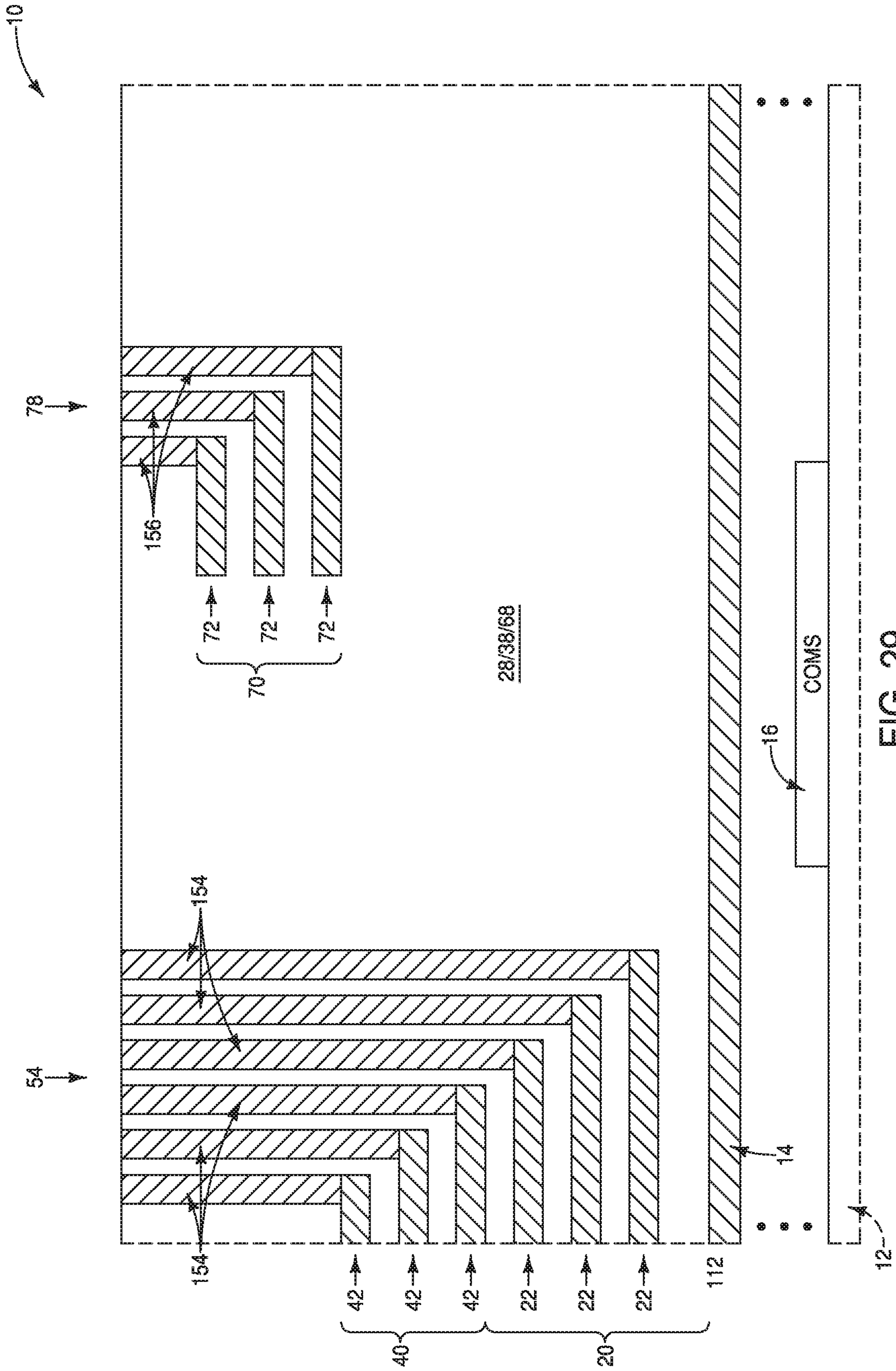


FIG. 29

INTEGRATED ASSEMBLIES AND METHODS OF FORMING INTEGRATED ASSEMBLIES

TECHNICAL FIELD

Integrated assemblies (e.g., NAND assemblies), and methods of forming integrated assemblies.

BACKGROUND

Memory provides data storage for electronic systems. Flash memory is one type of memory, and has numerous uses in modern computers and devices. For instance, modern personal computers may have BIOS stored on a flash memory chip. As another example, it is becoming increasingly common for computers and other devices to utilize flash memory in solid state drives to replace conventional hard drives. As yet another example, flash memory is popular in wireless electronic devices because it enables manufacturers to support new communication protocols as they become standardized, and to provide the ability to remotely upgrade the devices for enhanced features.

NAND may be a basic architecture of flash memory, and may be configured to comprise vertically-stacked memory cells.

Before describing NAND specifically, it may be helpful to more generally describe the relationship of a memory array within an integrated arrangement. FIG. 1 shows a block diagram of a prior art device **1000** which includes a memory array **1002** having a plurality of memory cells **1003** arranged in rows and columns along with access lines **1004** (e.g., wordlines to conduct signals WL_0 through WL_m) and first data lines **1006** (e.g., bitlines to conduct signals BL_0 through BL_n). Access lines **1004** and first data lines **1006** may be used to transfer information to and from the memory cells **1003**. A row decoder **1007** and a column decoder **1008** decode address signals A_0 through A_X on address lines **1009** to determine which ones of the memory cells **1003** are to be accessed. A sense amplifier circuit **1015** operates to determine the values of information read from the memory cells **1003**. An I/O circuit **1017** transfers values of information between the memory array **1002** and input/output (I/O) lines **1005**. Signals DQ_0 through DQ_n on the I/O lines **1005** can represent values of information read from or to be written into the memory cells **1003**. Other devices can communicate with the device **1000** through the I/O lines **1005**, the address lines **1009**, or the control lines **1020**. A memory control unit **1018** is used to control memory operations to be performed on the memory cells **1003**, and utilizes signals on the control lines **1020**. The device **1000** can receive supply voltage signals V_{cc} and V_{ss} on a first supply line **1030** and a second supply line **1032**, respectively. The device **1000** includes a select circuit **1040** and an input/output (I/O) circuit **1017**. The select circuit **1040** can respond, via the I/O circuit **1017**, to signals $CSEL_1$ through $CSEL_n$ to select signals on the first data lines **1006** and the second data lines **1013** that can represent the values of information to be read from or to be programmed into the memory cells **1003**. The column decoder **1008** can selectively activate the $CSEL_1$ through $CSEL_n$ signals based on the A_0 through A_X address signals on the address lines **1009**. The select circuit **1040** can select the signals on the first data lines **1006** and the second data lines **1013** to provide communication between the memory array **1002** and the I/O circuit **1017** during read and programming operations.

The memory array **1002** of FIG. 1 may be a NAND memory array, and FIG. 2 shows a block diagram of a

three-dimensional NAND memory device **200** which may be utilized for the memory array **1002** of FIG. 1. The device **200** comprises a plurality of strings of charge-storage devices. In a first direction ($Z-Z'$), each string of charge-storage devices may comprise, for example, thirty-two charge-storage devices stacked over one another with each charge-storage device corresponding to one of, for example, thirty-two tiers (e.g., Tier0-Tier31). The charge-storage devices of a respective string may share a common channel region, such as one formed in a respective pillar of semiconductor material (e.g., polysilicon) about which the string of charge-storage devices is formed. In a second direction ($X-X'$), each first group of, for example, sixteen first groups of the plurality of strings may comprise, for example, eight strings sharing a plurality (e.g., thirty-two) of access lines (i.e., "global control gate (CG) lines", also known as wordlines, WLs). Each of the access lines may couple the charge-storage devices within a tier. The charge-storage devices coupled by the same access line (and thus corresponding to the same tier) may be logically grouped into, for example, two pages, such as P_0/P_{32} , P_1/P_{33} , P_2/P_{34} and so on, when each charge-storage device comprises a cell capable of storing two bits of information. In a third direction ($Y-Y'$), each second group of, for example, eight second groups of the plurality of strings, may comprise sixteen strings coupled by a corresponding one of eight data lines. The size of a memory block may comprise 1,024 pages and total about 16 MB (e.g., $16\text{ WLs} \times 32\text{ tiers} \times 2\text{ bits} = 1,024\text{ pages/block}$, $\text{block size} = 1,024\text{ pages} \times 16\text{ KB/page} = 16\text{ MB}$). The number of the strings, tiers, access lines, data lines, first groups, second groups and/or pages may be greater or smaller than those shown in FIG. 2.

FIG. 3 shows a cross-sectional view of a memory block **300** of the 3D NAND memory device **200** of FIG. 2 in an $X-X'$ direction, including fifteen strings of charge-storage devices in one of the sixteen first groups of strings described with respect to FIG. 2. The plurality of strings of the memory block **300** may be grouped into a plurality of subsets **310**, **320**, **330** (e.g., tile columns), such as tile column', tile column_{*r*}, and tile column_{*K*}, with each subset (e.g., tile column) comprising a "partial block" of the memory block **300**. A global drain-side select gate (SGD) line **340** may be coupled to the SGDs of the plurality of strings. For example, the global SGD line **340** may be coupled to a plurality (e.g., three) of sub-SGD lines **342**, **344**, **346** with each sub-SGD line corresponding to a respective subset (e.g., tile column), via a corresponding one of a plurality (e.g., three) of sub-SGD drivers **332**, **334**, **336**. Each of the sub-SGD drivers **332**, **334**, **336** may concurrently couple or cut off the SGDs of the strings of a corresponding partial block (e.g., tile column) independently of those of other partial blocks. A global source-side select gate (SGS) line **360** may be coupled to the SGSs of the plurality of strings. For example, the global SGS line **360** may be coupled to a plurality of sub-SGS lines **362**, **364**, **366** with each sub-SGS line corresponding to the respective subset (e.g., tile column), via a corresponding one of a plurality of sub-SGS drivers **322**, **324**, **326**. Each of the sub-SGS drivers **322**, **324**, **326** may concurrently couple or cut off the SGSs of the strings of a corresponding partial block (e.g., tile column) independently of those of other partial blocks. A global access line (e.g., a global CG line) **350** may couple the charge-storage devices corresponding to the respective tier of each of the plurality of strings. Each global CG line (e.g., the global CG line **350**) may be coupled to a plurality of sub-access lines (e.g., sub-CG lines) **352**, **354**, **356** via a corresponding one of a plurality of sub-string

drivers **312**, **314** and **316**. Each of the sub-string drivers may concurrently couple or cut off the charge-storage devices corresponding to the respective partial block and/or tier independently of those of other partial blocks and/or other tiers. The charge-storage devices corresponding to the respective subset (e.g., partial block) and the respective tier may comprise a “partial tier” (e.g., a single “tile”) of charge-storage devices. The strings corresponding to the respective subset (e.g., partial block) may be coupled to a corresponding one of sub-sources **372**, **374** and **376** (e.g., “tile source”) with each sub-source being coupled to a respective power source.

The NAND memory device **200** is alternatively described with reference to a schematic illustration of FIG. **4**.

The memory array **200** includes wordlines **202₁** to **202_N**, and bitlines **228₁** to **228_M**.

The memory array **200** also includes NAND strings **206₁** to **206_M**. Each NAND string includes charge-storage transistors **208₁** to **208_N**. The charge-storage transistors may use floating gate material (e.g., polysilicon) to store charge, or may use charge-trapping material (such as, for example, silicon nitride, metallic nanodots, etc.) to store charge.

The charge-storage transistors **208** are located at intersections of wordlines **202** and strings **206**. The charge-storage transistors **208** represent non-volatile memory cells for storage of data. The charge-storage transistors **208** of each NAND string **206** are connected in series source-to-drain between a source-select device (e.g., source-side select gate, SGS) **210** and a drain-select device (e.g., drain-side select gate, SGD) **212**. Each source-select device **210** is located at an intersection of a string **206** and a source-select line **214**, while each drain-select device **212** is located at an intersection of a string **206** and a drain-select line **215**. The select devices **210** and **212** may be any suitable access devices, and are generically illustrated with boxes in FIG. **4**.

A source of each source-select device **210** is connected to a common source line **216**. The drain of each source-select device **210** is connected to the source of the first charge-storage transistor **208** of the corresponding NAND string **206**. For example, the drain of source-select device **210₁** is connected to the source of charge-storage transistor **208₁** of the corresponding NAND string **206₁**. The source-select devices **210** are connected to source-select line **214**.

The drain of each drain-select device **212** is connected to a bitline (i.e., digit line) **228** at a drain contact. For example, the drain of drain-select device **212₁** is connected to the bitline **228₁**. The source of each drain-select device **212** is connected to the drain of the last charge-storage transistor **208** of the corresponding NAND string **206**. For example, the source of drain-select device **212₁** is connected to the drain of charge-storage transistor **208_N** of the corresponding NAND string **206₁**.

The charge-storage transistors **208** include a source **230**, a drain **232**, a charge-storage region **234**, and a control gate **236**. The charge-storage transistors **208** have their control gates **236** coupled to a wordline **202**. A column of the charge-storage transistors **208** are those transistors within a NAND string **206** coupled to a given bitline **228**. A row of the charge-storage transistors **208** are those transistors commonly coupled to a given wordline **202**.

It is desired to develop improved NAND architecture and improved methods for fabricating NAND architecture.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. **1** shows a block diagram of a prior art memory device having a memory array with memory cells.

FIG. **2** shows a schematic diagram of the prior art memory array of FIG. **1** in the form of a 3D NAND memory device.

FIG. **3** shows a cross-sectional view of the prior art 3D NAND memory device of FIG. **2** in an X-X' direction.

FIG. **4** is a schematic diagram of a prior art NAND memory array.

FIGS. **5-10** are diagrammatic cross-sectional side views of a region of an integrated assembly at example sequential process stages of an example method for forming an example memory array.

FIG. **10A** is a diagrammatic cross-sectional side view of a region of FIG. **10**.

FIG. **10B** is a diagrammatic cross-sectional side view of a region similar to that of FIG. **10A** in accordance with another example embodiment.

FIGS. **11-19** are diagrammatic cross-sectional side views of the region of the integrated assembly of FIG. **5** at example sequential process stages of an example method for forming an example memory array. The process stage of FIG. **11** may follow that of FIG. **10**.

FIG. **19A** is a diagrammatic cross-sectional side view of a region of FIG. **19**.

FIG. **19B** is a diagrammatic top-down view of the region of FIG. **19A**.

FIG. **20** is a diagrammatic cross-sectional side view of the region of the integrated assembly of FIG. **5** at an example process stage subsequent to that of FIG. **19** of an example method for forming an example memory array.

FIG. **20A** is a diagrammatic cross-sectional side view of a region of FIG. **20**.

FIG. **20B** is a diagrammatic cross-sectional side view of a region similar to that of FIG. **20A** in accordance with another example embodiment.

FIGS. **21-26** are diagrammatic cross-sectional side views of the region of the integrated assembly of FIG. **5** at example sequential process stages of an example method for forming an example memory array. The process stage of FIG. **21** may follow that of FIG. **20**.

FIG. **26A** is a diagrammatic cross-sectional side view of a region similar to that of FIG. **26** in accordance with another example embodiment.

FIGS. **27** and **28** are diagrammatic cross-sectional side views of the region of the integrated assembly of FIG. **5** at example sequential process stages of an example method for forming an example memory array. The process stage of FIG. **27** may follow that of FIG. **26**.

FIG. **28A** is a diagrammatic top-down view of a region of the assembly of FIG. **28**.

FIG. **29** is a diagrammatic cross-sectional side view of another region of an integrated assembly showing example staircase regions.

DETAILED DESCRIPTION OF THE ILLUSTRATED EMBODIMENTS

Some embodiments include methods of forming memory with three or more decks stacked one atop another, and some embodiments include configurations having three or more decks stacked one atop another. Example embodiments are described with reference to FIGS. **5-29**. It is noted that many of the cross-sectional side views show multiple regions which are not generally in the same plane as one another, but which are shown in the same plane to simplify the drawings. Such will be explained in greater detail below relative to FIGS. **28** and **28A**.

Referring to FIG. **5**, an assembly **10** includes a conductive structure **14** supported by a base **12**.

The conductive structure **14** may be a source structure analogous to the source structures **216** and **360** described above in the Background section. The conductive structure **14** may comprise any suitable electrically conductive composition(s), and in some embodiments may comprise conductively-doped semiconductor material. The conductively-doped semiconductor material may be conductively-doped silicon (e.g., n-type silicon). The conductively-doped semiconductor material of the source structure **14** may be over one or more additional conductive materials of the source structure **14** (e.g., one or more metal-containing materials, such as, for example, one or both of tungsten and tungsten silicide).

The base **12** may comprise semiconductor material; and may, for example, comprise, consist essentially of, or consist of monocrystalline silicon. The base **12** may be referred to as a semiconductor substrate. The term “semiconductor substrate” means any construction comprising semiconductive material, including, but not limited to, bulk semiconductive materials such as a semiconductive wafer (either alone or in assemblies comprising other materials), and semiconductive material layers (either alone or in assemblies comprising other materials). The term “substrate” refers to any supporting structure, including, but not limited to, the semiconductor substrates described above. In some applications, the base **12** may correspond to a semiconductor substrate containing one or more materials associated with integrated circuit fabrication. Such materials may include, for example, one or more of refractory metal materials, barrier materials, diffusion materials, insulator materials, etc.

The base **12** is spaced from the conductive structure **14** by a gap. Such gap is utilized to indicate that there may be one or more additional components, structures, etc., between the conductive structure **14** and the base **12**. In the illustrated embodiment, logic circuitry (e.g., CMOS) **16** is supported by the base **12**, and is within the gap between the base **12** and the conductive structure **14**. The conductive structure **14** is shown to be electrically coupled to the CMOS.

In the illustrated embodiment of FIG. **5**, additional conductive structures **18** are laterally adjacent to the source structure **14**. The additional conductive structures **18** are also electrically coupled with the CMOS **16**. The additional conductive structures may be conductive landing pads utilized to couple conductive features (some of which are described below with reference to FIG. **22**) with the CMOS **16**. Although all of the conductive structures **18** are shown to be electrically coupled with the CMOS, in other embodiments one or more of the structures **18** may not be coupled with the CMOS. The structures **18** which are not coupled with the CMOS may be provided as support structures.

A stack **20** of alternating first and second tiers (levels, layers) **22** and **24** is formed over the conductive structures **14** and **18**. The stack **20** may comprise any suitable number of alternating tiers **22** and **24**. The tiers **22** ultimately become conductive levels of a memory arrangement. There may be any suitable number of tiers **22** to form the desired number of conductive levels. In some embodiments, the number of tiers **22** may be 8, 16, 32, 64, etc.

The first tiers **22** comprise a first material **26**. Such first material may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon nitride.

The second tiers **24** comprise a second material **28**. Such material may be an insulative material and may comprise

any suitable composition(s). In some embodiments, the material **28** may comprise, consist essentially of, or consist of silicon dioxide.

In some embodiments, the materials **26** and **28** may be referred to as a first material and an insulative second material, respectively.

The tiers **22** and **24** may be of any suitable thicknesses; and may be the same thickness as one another, or may be different thicknesses relative to one another. In some embodiments, the tiers **22** and **24** may have vertical thicknesses within a range of from about 10 nanometers (nm) to about 400 nm. In the illustrated embodiment, the bottommost tier **24** is thicker than the other tiers **24**. In other embodiments, the bottommost tier **24** may have a thickness which is about the same as the thickness of the other tiers **24**, or may be less thick than the other tiers **24**.

In some embodiments, the stack **20** may be referred to as a first stack to distinguish it from additional stacks formed at later process stages. The first stack **20** may be considered to be comprised by a first deck **30**.

Referring to FIG. **6**, first openings **32** are formed to extend through the first stack **20**. In the shown embodiment, the first openings **20** extend downwardly to an upper surface of the source structure **14**.

Referring to FIG. **7**, sacrificial material **34** is formed within the first openings **32**. The sacrificial material **34** may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of one or more of metal (e.g., tungsten), undoped semiconductor material (e.g., doped silicon), etc.

In the shown embodiment, a planarized surface **35** is formed to extend across the sacrificial material **34** and the upper tier **24**. The planarized surface **35** may be formed with any suitable processing, including, for example, chemical-mechanical polishing (CMP).

Referring to FIG. **8**, a second stack **40** of alternating third and fourth tiers (levels, layers) **42** and **44** is formed over the first stack **20**. The stack **40** may comprise any suitable number of alternating tiers **42** and **44**. The tiers **42** ultimately become conductive levels of a memory arrangement. There may be any suitable number of tiers **42** to form the desired number of conductive levels. In some embodiments, the number of tiers **42** may be 8, 16, 32, 64, etc.

The third tiers **42** comprise a third material **36**. Such third material may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon nitride. Accordingly, the third material **36** may comprise a same composition as the first material **26**.

The fourth tiers **44** comprise a fourth material **38**. Such material may be an insulative material and may comprise any suitable composition(s). In some embodiments, the fourth material **38** may comprise, consist essentially of, or consist of silicon dioxide. In some embodiments, the insulative fourth material **38** may comprise a same composition as the insulative second material **28**.

The tiers **42** and **44** may have the same thicknesses described above relative to the tiers **22** and **24**.

The second stack **40** may be considered to be comprised by a second deck **50**.

Referring to FIG. **9**, second openings **46** are formed to extend through the second stack **40** to the first openings **32**. In the shown embodiment, the second openings **46** extend to the sacrificial material **34** within the first openings **32**.

The second openings **46** are misaligned relative to the first openings **32** in the illustrated embodiment of FIG. **9**. In other embodiments, the second openings **46** may be aligned relative to the first openings **32**.

Referring to FIG. 10, additional sacrificial material 34 is formed within the second openings 46. The sacrificial material 34 within the openings 32 and 46 forms sacrificial structures 48.

An inter-deck region 51 is diagrammatically indicated in FIG. 10. The structures 48 have inter-deck inflections 52 within the inter-deck region 51. FIG. 10A shows an enlarged view of a segment of one of the structures 48 within the inter-deck region 51 to more clearly illustrate the example inter-deck inflection 52. The illustrated inter-deck inflection 52 occurs where the opening 46 (the opening formed through the second deck 50) meets the opening 32 (the opening formed through the first deck 30), and is a result of the misalignment of the openings 46 and 32. Specifically, the inter-deck inflection 52 of FIG. 10A corresponds to a region where an upper portion of the sacrificial-material-structure 48 is laterally offset relative to a lower portion of the sacrificial-material-structure 48.

FIG. 10A shows an example of an inter-deck inflection that may be detected in a structure (e.g., structure 48) passing through two decks in a location where the decks join to one another. The inter-deck inflection results from one portion of the structure being formed during fabrication associated with the lower deck and another portion of the structure being formed during fabrication associated with the upper deck.

The inter-deck inflection may be considered to correspond to any detectable change in a region of a structure passing through an interface between two decks. Another example configuration of an inter-deck inflection 52 is shown in FIG. 10B. The configuration of FIG. 10B has the second opening 48 aligned with the first opening 32. However, the first and second openings are tapered during formation of such openings, and accordingly the inflection 52 occurs where a narrow portion of the tapered opening 48 joins to a wide portion of the tapered opening 32 within the inter-deck region 51.

Referring again to FIG. 10, a planarized surface 45 is formed across the sacrificial material 34 and the upper tier 44. The planarized surface 45 may be formed with any suitable processing, including, for example, CMP.

Referring to FIG. 11, a staircase opening 54 is formed to extend into the first and second stacks 20 and 40. In the illustrated embodiment, the staircase opening 54 extends to the lowermost of the first tiers 22 within the first deck 30.

Referring to FIG. 12, sacrificial material 56 is formed within the staircase opening 54. The sacrificial material 56 may comprise any suitable composition(s), and in some embodiments may comprise a same composition as the sacrificial material 34.

A planarized surface 57 is formed to extend across the sacrificial material 56 and the uppermost tier 44. The surface 57 may be formed with any suitable processing, such as, for example, CMP.

Referring to FIG. 13, openings 58, 60, 62 and 64 are formed to extend through the first and second decks 30 and 50, and to an upper surface of the conductive structure 14. In some embodiments, one or more of the openings 58, 60, 62 and 64 may extend into the conductive structure 14. In the illustrated embodiment, the materials 26 and 36 are recessed along sidewalls of the openings 58, 60, 62 and 64. Such recessing may be advantageous to increase the dimensions of the openings at locations along the tiers 22 and 42. In other embodiments, the materials 26 and 36 may not be recessed. Accordingly, the openings 58, 60, 62 and 64 may have substantially straight sidewalls rather than the illustrated undulating sidewalls.

The openings 58 may correspond to slits extending in and out of the page relative to the cross-sectional view of FIG. 13, as explained in more detail below with reference to FIG. 28A. The openings 60, 62 and 64 may have substantially the same configuration as one another (i.e., maybe circular, square-shaped, etc., when viewed from above, and may be about the same dimensions as one another), or may comprise different configurations relative to one another. The openings 60, 62 and 64 may be utilized for forming different structures relative to one another, and accordingly are given different labels relative to one another.

Referring to FIG. 14, sacrificial material 66 is formed within the openings 58, 60, 62 and 64. The sacrificial material 66 may comprise any suitable composition(s), and in some embodiments may comprise a same composition as the sacrificial material 34. In some embodiments, the sacrificial material 66 may comprise insulative material (e.g., porous silicon dioxide, carbon-doped silicon dioxide, silicon oxynitride, etc.).

An insulative material 68 is formed over the sacrificial material 66 and the uppermost tier 42. The insulative material 68 may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon dioxide. Accordingly, in some embodiments the insulative material 68 may comprise a same composition as the materials 28 and 38 of the tiers 24 and 44, and may comprise a same composition as the material 56.

The insulative material 68 is shown to have a planarized upper surface 69. The planarized surface 69 may be formed with any suitable processing, such as, for example, CMP.

The insulative material 68 may be considered formed over the second deck 50 (the second stack 40). In some embodiments, the insulative material 68 may be considered to be a tier 74 which is formed over the uppermost tier 42 of the stack 40.

Referring to FIG. 15, a third stack 70 of alternating fifth and sixth tiers (levels, layers) 72 and 74 is formed over the second stack 40. In some embodiments, the insulative material 68 may be considered to be one of the tiers 74 of the third stack 70.

The stack 70 may comprise any suitable number of alternating tiers 72 and 74. The tiers 72 ultimately become conductive levels of a memory arrangement. There may be any suitable number of tiers 72 to form the desired number of conductive levels. In some embodiments, the number of tiers 72 may be 8, 16, 32, 64, etc.

The fifth tiers 72 comprise a fifth material 76. Such fifth material may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon nitride. Accordingly, the fifth material 76 may comprise a same composition as the first and third materials 26 and 36.

The sixth tiers 74 comprise the insulative material 68. In some embodiments, the insulative material 68 may be referred to as an insulative sixth material. The insulative sixth material 68 may comprise a same composition as the insulative second material 28 and the insulative fourth material 38.

The tiers 72 and 74 may have the same thicknesses described above relative to the tiers 22 and 24. In the shown embodiment, the lowermost tier 74 (i.e., the tier formed at the process stage of FIG. 14) is thicker than the other tiers 74 within the stack 70.

The third stack 70 may be considered to be comprised by a third deck 80.

Referring to FIG. 16, a second staircase opening 78 is formed to extend into the third stack 70. In the illustrated

embodiment, the second staircase opening extends to the bottommost tier **72** of the third stack.

FIG. **16** also shows the third stack **70** patterned so that the first staircase opening **54** passes through the third stack. In the illustrated embodiment, the sacrificial material **56** (FIG. **15**) is removed at the process stage of FIG. **16**. In other embodiments, the material **56** may correspond to insulative material (e.g., silicon dioxide), and may remain at the process stage of FIG. **16** rather than being removed.

Referring to FIG. **17**, insulative material **82** is formed within the staircase openings **54** and **78**. The insulative material **82** may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon dioxide. A planarized surface may be formed to extend across the insulative material **82** and the uppermost tier **74**.

Referring to FIG. **18**, third openings **84** are formed through the third stack **70** to the second openings **46**, and the sacrificial material **34** (FIG. **17**) is removed from within the first and second openings **32** and **46**.

The third openings **84** are misaligned relative to the second openings **46** in the illustrated embodiment of FIG. **18**. In other embodiments, the third openings **84** may be aligned relative to the second openings **46**.

An inter-deck region **81** is diagrammatically indicated in FIG. **18**. The regions wherein the openings **84** join to the openings **46** have inter-deck inflections **86** within the inter-deck region **81**. The inter-deck inflections **86** may be analogous to the inter-deck inflections described above with reference to FIG. **10A**. In other embodiments the inter-deck inflections **86** may have other configurations, such as, for example, configurations analogous to the configuration described above with reference to FIG. **10B**.

Referring to FIG. **19**, channel-material-pillars **88** are formed within the openings **32**, **46** and **84**. The channel material pillars **88** may be considered to extend vertically through the first, second and third decks **30**, **50** and **80**, and are shown to be electrically coupled with the conductive structure **14** (and in the shown embodiment are directly against the conductive structure **14**). The channel-material-pillars **88** are shown to be hollow, and to laterally surround insulative material **90**. The channel material-pillars **88** are offset from edges of the openings **84**, **46** and **32** by regions **92** comprising cell materials. The channel-material-pillars **88** and cell materials are shown in more detail relative to enlarged views of FIGS. **19A** and **19B**.

The channel-material-pillars **88** comprise channel material **94**. The channel material **94** may comprise any suitable semiconductor composition(s). In some embodiments, the channel material **94** may comprise, consist essentially of, or consist of one or more of silicon, germanium, III/V semiconductor material (e.g., gallium phosphide), semiconductor oxide, etc.; with the term III/V semiconductor material referring to semiconductor materials comprising elements selected from groups III and V of the periodic table (with groups III and V being old nomenclature, and now being referred to as groups **13** and **15**). In some embodiments, the channel material **94** may comprise silicon. The silicon may be in any suitable crystalline state (e.g., monocrystalline, polycrystalline, amorphous, etc.).

The cell materials within the regions **92** may include gate-dielectric material (insulative material, tunneling material) **96**, charge-storage material **98**, charge-blocking material **100** and dielectric-barrier material **102**. The gate-dielectric material **96** is shown to be adjacent to the channel-material-pillar **98**, and in the illustrated embodiment is directly against the channel-material-pillar.

The gate-dielectric material **96** may comprise any suitable composition(s); and in some embodiments may comprise one or more of silicon dioxide, silicon nitride, aluminum oxide, hafnium oxide, zirconium oxide, etc. In some embodiments, the material **96** may comprise a bandgap-engineered laminate.

The charge-storage material **98** may comprise any suitable composition(s), and in some embodiments may comprise charge-trapping material (e.g., one or more of silicon nitride, silicon oxynitride, conductive nanodots, etc.).

The charge-blocking material **100** comprise any suitable composition(s), and some embodiments may comprise one or both of silicon dioxide and silicon oxynitride.

The dielectric-barrier material **102** may comprise any suitable composition(s); and may, for example, comprise one or more high-k compositions (e.g., aluminum oxide, hafnium oxide, zirconium oxide, etc.). The term "high-k composition" means a composition having a dielectric constant greater than the dielectric constant associated with silicon dioxide (i.e., greater than about 3.9).

The insulative material **90** may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon dioxide. In some embodiments, the insulative material **90** may be omitted and the channel-material-pillars **88** may be solid pillars, rather than being the illustrated hollow pillars.

The processing of FIGS. **16-19** shows the staircase openings **54** and **78** patterned in the third deck **80** prior to forming the pillars **88** and the cell materials (i.e., the staircase regions are defined in the third deck prior to forming the pillars **88** to extend through the third deck). In other embodiments, the openings **84** (FIG. **18**) may be formed to extend through the third deck, and the pillars **88** and cell materials formed within such openings, prior to patterning the staircase regions within the third deck.

The processing of FIGS. **6-19** comprises formation of the sacrificial material **34** (FIG. **12**) within the first and second openings **32** and **46** of the first and second decks **30** and **50** to hold locations for the channel-material-pillars **88**, followed by removal of such sacrificial material to form openings which extend through all three of the decks at the process stage of FIG. **18**, and then formation of the channel-material-pillars within the openings. In other embodiments, portions of the channel material pillars may be formed at one or more of the process steps prior to the process step of FIG. **19**. For instance, first portions (first regions) of the channel-material-pillars may be formed at the process stage of FIG. **7** instead of forming the sacrificial material **34**, and second portions (second regions) of the channel-material-pillars may be formed at the process stage of FIG. **10** instead of forming the sacrificial material **34**. Alternatively, the sacrificial material **34** may be formed at the process stage of FIG. **7**, and then such sacrificial material may be removed at the process stage of FIG. **10** and the first portions (first regions) of the channel-material-pillars may be formed to extend through both of the first and second decks **30** and **50** at the process stage of FIG. **10**.

The sacrificial material **66** of FIG. **19** is shown to form structures having upper surfaces **67**. Such upper surfaces are formed during the fabrication of the second deck **50**, and accordingly may be considered to be associated with the second deck **50** (the second stack **40**).

Referring to FIG. **20**, the third stack **70** is patterned to extend the openings **58**, **60**, **62** and **64** (described above with reference to the process stage of FIG. **13**) through the third stack, and then additional sacrificial material **66** is formed within extended openings.

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Portions of the inter-deck region **81** are diagrammatically indicated in FIG. **20**. The openings **58**, **60**, **62** and **64** extend through the inter-deck region **81**. In the shown embodiment, the portions of the openings **58**, **60**, **62** and **64** within the third deck **80** are aligned with the portions within the first and second decks **30** and **50** so that inter-deck inflections are not present within the openings **58**, **60**, **62** and **64**. In other embodiments, inter-deck inflections may be present within the openings **58**, **60**, **62** and **64** along the inter-deck region **81**. FIG. **20A** shows an enlarged view along one of the openings **58**, **60**, **62** and **64** at the process stage of FIG. **20**, and shows that there is no inter-deck inflection along the inter-deck region **81**. FIG. **20B** shows a view of the same region in accordance with an embodiment in which the opening within the third deck **80** is not aligned with the opening within the second deck **50**, and accordingly in which an inter-deck inflection **104** is formed along the inter-deck region **81**. The illustrated inter-deck inflection **104** corresponds to a region where the portion of the opening through the upper deck **80** is laterally offset relative to the portion of the opening within the lower deck **50**. In other embodiments the inter-deck inflection may have another configuration, such as, for example, a configuration analogous to the configuration described above with reference to FIG. **10B**.

In some embodiments, the sacrificial material **66** within the openings **58**, **60**, **62** and **64** may be considered to be configured as features **108**, **110**, **112** and **114**. The features **108** may correspond to panels extending in and out of the page relative to the cross-sectional view of FIG. **20**, and the features **110**, **112** and **114** may correspond to pillars. Each of the features has a first portion which extends through the first and second stacks **20** and **40**, and which is formed after forming the second stack (with such first portions being shown at the process stage of FIG. **19**, and having the upper surfaces **67**); and each of the features has a second portion which extends through the third stack **70** and which is formed directly against the first portion (with the second portions being shown in FIG. **20**). Example first and second portions are shown in FIGS. **20A** and **20B** as portions **116** and **118**, respectively. The portions **116** and **118** join to one another along the inter-deck region **81**. In the embodiment of FIG. **20A** there is no inter-deck inflection where the portions **116** and **118** join to one another. In contrast, FIG. **20B** shows an inter-deck inflection where the portion **116** joins to the portion **118**.

Referring to FIG. **21**, the features **114** (FIG. **20**) within the openings **64** are removed. Remaining portions of the assembly **10** may be protected with a mask (not shown) while the sacrificial material **66** of the features **114** is removed.

Referring to FIG. **22**, the openings **64** are lined with insulative material **122**, and then conductive material **120** is formed within the lined openings. The insulative material **122** may comprise any suitable composition(s), and in some embodiments may comprise silicon dioxide. The conductive material **120** may comprise any suitable electrically conductive composition(s); such as, for example, one or more of various metals (e.g., titanium, tungsten, cobalt, nickel, platinum, ruthenium, etc.), metal-containing compositions (e.g., metal silicide, metal nitride, metal carbide, etc.), and/or conductively-doped semiconductor materials (e.g., conductively-doped silicon, conductively-doped germanium, etc.).

In some embodiments, the processing of FIGS. **21** and **22** may be considered to replace at least some of the sacrificial material **66** of the features **114** (FIG. **20**) with the conductive material **120**.

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The conductive material **120** within the openings **64** is configured as conductive interconnects **124** which extend through the decks **30**, **50** and **80**, and to a pair of the conductive structures **18**. The conductive interconnects **124** may be “live” interconnects utilized for coupling circuitry to the CMOS **16** through the conductive structures **18**. In the illustrated embodiment, one of the sacrificial structures **112** remains over one of the conductive structures **18**. The conductive structure **18** under the sacrificial structure **112** may or may not be coupled with the CMOS **16**. In some embodiments (not shown) a conductive structure analogous to the structure **124** may be formed over a conductive structure **18** and may not be electrically coupled to the CMOS **16**. Instead such conductive structure **124** may be used solely as a support structure (a “dummy” structure) rather than as a “live” structure.

Referring to FIG. **23**, the sacrificial material **66** is removed from within the openings **58** and **62**.

Referring to FIG. **24**, etchant (not shown) is flowed into the openings **58** and **62**, and is utilized to remove the materials **26**, **36** and **76** (shown in FIG. **23**) to form voids **126** along the levels **22**, **42** and **72**.

Referring to FIG. **25**, conductive material **128** is formed within the voids **126** (FIG. **24**). The conductive material **128** may comprise any suitable electrically conductive composition(s); such as, for example, one or more of various metals (e.g., titanium, tungsten, cobalt, nickel, platinum, ruthenium, etc.), metal-containing compositions (e.g., metal silicide, metal nitride, metal carbide, etc.), and/or conductively-doped semiconductor materials (e.g., conductively-doped silicon, conductively-doped germanium, etc.), and may comprise a metal-containing composition (e.g., metal nitride, metal carbide, metal silicide, etc.). In some embodiments, the conductive material **128** may comprise a metal-containing core (e.g., a tungsten-containing core), and a metal nitride (e.g., titanium nitride, tungsten nitride, etc.) along a periphery of the metal-containing core. In some embodiments, dielectric-barrier material may be formed within the voids **126** (FIG. **24**) prior to forming the conductive material **128** within the voids. In such embodiments, the dielectric-barrier material **102** (FIGS. **19A** and **19B**) may not be formed within the openings **32**, **46** and **84** of FIG. **18**.

The alternating levels **22** and **24** of the first stack **20** may be referred to as first conductive levels and first insulative levels, respectively; the alternating levels **42** and **44** of the second stack **40** may be referred to as second conductive levels and second insulative levels, respectively; and the alternating levels **72** and **74** of the third stack **70** may be referred to as third conductive levels and third insulative levels, respectively.

The processing of FIGS. **24** and **25** may be considered to replace at least some of the first, third and fifth materials **26**, **36** and **76** (FIG. **23**) with one or more conductive materials (e.g., the conductive material **128**) to form the first, second and third conductive levels **22**, **42** and **72** of FIG. **25**.

Referring to FIG. **26**, panels **130** are formed within the slits corresponding to the openings **58**. In the shown embodiment, the panels **130** comprise insulative edge structures **132**, and conductive central structures **134**. The insulative structures **132** may comprise any suitable composition(s); and in some embodiments may comprise, consist essentially of, or consist of silicon dioxide. The central structures **134** may comprise any suitable electrically conductive composition(s); such as, for example, one or more of various metals (e.g., titanium, tungsten, cobalt, nickel, platinum, ruthenium, etc.), metal-containing compositions (e.g., metal silicide, metal nitride, metal carbide, etc.), and/or conductively-

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doped semiconductor materials (e.g., conductively-doped silicon, conductively-doped germanium, etc.). In some embodiments, the central structures **134** may comprise, consist essentially of, or consist of appropriately-doped silicon.

Insulative material **140** is formed within the openings **62**. The insulative material **140** may comprise any suitable composition(s), and in some embodiments may comprise, consist essentially of, or consist of silicon dioxide.

In some embodiments, panels **130** may be considered to replace the sacrificial features **108** (FIG. **22**), and the insulative material **140** may be considered to form insulative features **142** which replace the sacrificial features **112** (FIG. **22**). One of the insulative features **142** is over one of the conductive structures **18**. Such conductive structure may or may not be coupled with the CMOS **16**.

FIG. **26A** shows an alternative embodiment relative to that of FIG. **26**. Specifically, the panels **130** comprise only insulative material, rather than also comprising the conductive central regions **134**. In the illustrated embodiment, the panels **130** comprise the same insulative material **140** as is utilized in the insulative structures **142**.

FIG. **27** shows the assembly **10** at a process stage subsequent to that of FIG. **26**. Openings **150** are formed to extend into the first and second staircase regions **54** and **78**. An insulative material (not shown) may be formed over an upper surface of the assembly **10** prior to forming the openings **150**.

Referring to FIG. **28**, conductive material **152** is formed within the openings **150**. The conductive material **152** forms a first interconnect **154** in the first staircase region **54**, with such first interconnect extending to one of the conductive levels within the stacks **20** and **40**. In the illustrated embodiment, the interconnect **154** extends to the bottommost conductive level. Other interconnects (described below with reference to FIG. **29**) may be formed to extend to other levels within the stacks **20** and **40**.

The conductive material **152** forms a second interconnect **156** within the second staircase region **78**, with such second interconnect extending to one of the conductive levels within the third stack **70**. In the shown embodiment, the interconnect **156** extends to the bottommost conductive level of the stack **70**. Other interconnects (described below with reference to FIG. **29**) may be formed to extend to other levels within the stack **70**.

The inter-deck regions **51** and **81** are diagrammatically illustrated in FIG. **28**. Such regions may be considered to be boundaries between adjacent decks, with the region **51** being a boundary between the first and second decks **30** and **50**, and the region **81** being a boundary between the second and third decks **50** and **80**.

The channel-material-pillars **88** may be considered to correspond to first features which pass through the first, second and third decks. Each of such first features has two inter-deck inflections, as described above with reference to FIGS. **10** and **18**. One of the inter-deck inflections is an inflection **52** in the first inter-deck region **51**, and the other is an inflection **86** in the inter-deck region **81**.

One or more of the panels **130**, insulative structures **142** and conductive interconnects **124** may be considered to be a second feature passing through the first, second and third decks. The second feature has no inter-deck inflection associated with the first inter-deck region **51**, and may or may not have an inter-deck inflection associated with the second region **81** (as described above with reference to FIGS. **20**, **20A** and **20B**).

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First memory cells **15** are along the first conductive levels **22**, second memory cells **17** are along the second conductive levels **42**, and third memory cells **19** are along the third conductive levels **72**. Each of the first, second and third memory cells includes a portion of a channel-material-pillar **88**, portions of the memory cell materials adjacent the channel-material-pillar (with the memory cell materials been described above with reference to FIGS. **19A** and **19B**), and portions of the conductive levels. The memory cells **15**, **17** and **19** along the pillars **88** may correspond to vertical strings of memory cells suitable for utilization in NAND memory of the types described above with reference to FIGS. **1-4**.

The bottom conductive level **22** of the first deck **20** are shown to comprise source-side select gate (SGS) devices **160** rather than comprising memory cells. In some embodiments, more than one conductive level may be incorporated into the SGS devices. If multiple conductive levels are incorporated into the SGS devices, the conductive levels may be electrically ganged together.

The first memory cells **15** may be considered to be arranged in first tiers (the levels **22**), with such first tiers being disposed one atop another and being comprised by the first deck **30**. The second memory cells **17** may be considered to be arranged in second tiers (the levels **42**), with such second tiers being disposed one atop another and being comprised by the second deck **50**. The third memory cells **19** may be considered to be arranged in third tiers (the levels **72**) with such third tiers being disposed one atop another and being comprised by the third deck **80**.

The various features within the view of FIG. **28** may be within multiple planes of an assembly. The various planes are separated from one another, and are indicated to be within regions designated as **Z1**, **Z2**, **Z3** and **Z4**.

FIG. **28A** shows a top-down view of the assembly **10** diagrammatically illustrating an example arrangement of the various structures shown in FIG. **28**. The channel-material-pillars **88** may be considered to be arranged in a memory block **170** analogous to the block regions described above with reference to FIGS. **1-4**. The panels **130** may correspond to structures which separate one block region from another. For instance, a second block region **172** may be on opposing side of one the panels **130** from the first block region **170**. In some embodiments, each of the channel-material-pillars **88** may be substantially identical to the others (with the term "substantially identical" meaning identical to within reasonable tolerances of fabrication and measurement). The panels **130** may include a first panel **130** along a first lateral edge of the memory block **170**, and a second panel **130** along a second lateral edge of the memory block (with said second lateral edge of the memory block being in opposing relation to said first lateral edge of the memory block).

The view of FIG. **28A** shows an example configuration of the various features. Other configurations may be utilized in other embodiments.

The interconnects **124** of FIGS. **28** and **28A** may couple circuitry above the memory cells (**15**, **17**, **19**) with the CMOS circuitry **16**. For instance, the interconnects **124** may be coupled with drain-side select gate (SGD) circuitry, bitline circuitry, etc. Alternatively, or additionally, the interconnects **124** may extend to circuitry which is laterally outward of the illustrated region of the assembly **10**.

The staircase regions **54** and **78** of FIGS. **28** and **28A** may be utilized for connecting to multiple tiers within the stacks **20**, **40** and **70**. FIG. **29** diagrammatically illustrates portions of the staircase regions **54** and **78** in an alternative view relative to that of FIG. **28**. The interconnects **154** within the

staircase region **54** extend to multiple conductive levels **22** and **42** within the stacks **20** and **40**. The interconnects **156** within the staircase region **78** extend to multiple conductive levels **72** within the stack **70**. The insulative material of FIG. **29** is labeled as **28/38/68** to indicate that such insulative material may comprise one or more of the materials **28**, **38** and **68**.

The embodiments described herein advantageously enable staircase regions to be efficiently formed relative to the multiple stacked levels of the illustrated decks. It may be problematic to form three separate staircase regions to reach the conductive levels of each of the illustrated three stacked decks as such may be inefficient relative to the number of patterning steps (and accordingly may have unnecessary costs), and may utilize a substantial amount of semiconductor real estate. Alternatively, it may be problematic to utilize only a single staircase region to reach the multiple levels of all three of the illustrated three stacked decks in that the lowermost levels are too deep to reach efficiently with conventional etch processes. Embodiments described herein advantageously utilize a first staircase region to reach the stacks associated with two of the decks, and utilize a second staircase region to reach the stack associated the third of the decks. Accordingly, such embodiments avoid the problems associated with utilizing separate staircase regions for each deck (i.e., three separate staircase regions), and avoid the problems associated with utilizing only a single staircase region for all of the decks.

In some aspects, embodiments described herein may be detected in final structures due to asymmetry present between the vertical configuration of the channel-material-pillars (**88**) and the vertical configuration of other features besides the channel-material-pillars, with examples of such other features being the panels **130**, the support structures **142**, and the interconnects (“live” structures) **124**.

Although the embodiments described herein show three stacked decks, it is to be understood that in other applications such embodiments may be extended to configurations having more than three stacked decks.

The assemblies and structures discussed above may be utilized within integrated circuits (with the term “integrated circuit” meaning an electronic circuit supported by a semiconductor substrate); and may be incorporated into electronic systems. Such electronic systems may be used in, for example, memory modules, device drivers, power modules, communication modems, processor modules, and application-specific modules, and may include multilayer, multi-chip modules. The electronic systems may be any of a broad range of systems, such as, for example, cameras, wireless devices, displays, chip sets, set top boxes, games, lighting, vehicles, clocks, televisions, cell phones, personal computers, automobiles, industrial control systems, aircraft, etc.

Unless specified otherwise, the various materials, substances, compositions, etc. described herein may be formed with any suitable methodologies, either now known or yet to be developed, including, for example, atomic layer deposition (ALD), chemical vapor deposition (CVD), physical vapor deposition (PVD), etc.

The terms “dielectric” and “insulative” may be utilized to describe materials having insulative electrical properties. The terms are considered synonymous in this disclosure. The utilization of the term “dielectric” in some instances, and the term “insulative” (or “electrically insulative”) in other instances, may be to provide language variation within this disclosure to simplify antecedent basis within the claims that follow, and is not utilized to indicate any significant chemical or electrical differences.

The terms “electrically connected” and “electrically coupled” may both be utilized in this disclosure. The terms are considered synonymous. The utilization of one term in some instances and the other in other instances may be to provide language variation within this disclosure to simplify antecedent basis within the claims that follow.

The particular orientation of the various embodiments in the drawings is for illustrative purposes only, and the embodiments may be rotated relative to the shown orientations in some applications. The descriptions provided herein, and the claims that follow, pertain to any structures that have the described relationships between various features, regardless of whether the structures are in the particular orientation of the drawings, or are rotated relative to such orientation.

The cross-sectional views of the accompanying illustrations only show features within the planes of the cross-sections, and do not show materials behind the planes of the cross-sections, unless indicated otherwise, in order to simplify the drawings.

When a structure is referred to above as being “on”, “adjacent” or “against” another structure, it can be directly on the other structure or intervening structures may also be present. In contrast, when a structure is referred to as being “directly on”, “directly adjacent” or “directly against” another structure, there are no intervening structures present. The terms “directly under”, “directly over”, etc., do not indicate direct physical contact (unless expressly stated otherwise), but instead indicate upright alignment.

Structures (e.g., layers, materials, etc.) may be referred to as “extending vertically” to indicate that the structures generally extend upwardly from an underlying base (e.g., substrate). The vertically-extending structures may extend substantially orthogonally relative to an upper surface of the base, or not.

Some embodiments include an integrated assembly having a first deck with first memory cells arranged in first tiers disposed one atop another, a second deck over the first deck, and a third deck over the second deck. The second deck has second memory cells arranged in second tiers disposed one atop another, and the third deck has third memory cells arranged in third tiers disposed one atop another. A first feature passes through the first, second and third decks. The first feature has two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks. A second feature passes through the first, second and third decks. The second feature has no inter-deck inflection associated with the boundary between the first and second decks.

Some embodiments include an integrated assembly having a first deck, a second deck over the first deck, and a third deck over the second deck. The first deck has first conductive levels disposed one atop another. The second deck has second conductive levels disposed one atop another. The third deck has third conductive levels disposed one atop another. A first staircase region extends to the first and second conductive levels, and passes through the third conductive levels. A second staircase region extends to the third conductive levels and not to the first and second conductive levels.

Some embodiments include a method of forming an integrated assembly. A first stack of alternating first and second tiers is formed over a conductive structure. The first and second tiers comprise a first material and an insulative second material, respectively. A first opening is formed to

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extend through the first stack. A second stack of alternating third and fourth tiers is formed over the first stack. The third and fourth tiers comprise a third material and an insulative fourth material, respectively. A second opening is formed to extend through the second stack to the first opening. A first staircase opening is formed to extend into the first and second stacks. A third stack of alternating fifth and sixth tiers is formed over the second stack. The fifth and sixth tiers comprise a fifth material and an insulative sixth material, respectively. A third opening is formed to extend through the third stack to the second opening. A region of the third stack is patterned to pass the first staircase opening through the third stack. A second staircase opening is formed to extend into the third stack. A channel-material-pillar is formed within the first, second and third openings. The channel-material-pillar extends vertically through the first, second and third stacks and is electrically coupled with the conductive structure. At least some of the first, third and fifth materials is replaced with one or more conductive materials to thereby convert the first, third and fifth tiers to first, second and third conductive levels, respectively. A first interconnect is formed to extend to one of the first and second conductive levels through the first staircase opening. A second interconnect is formed to extend to one of the third conductive levels through the second staircase opening.

In compliance with the statute, the subject matter disclosed herein has been described in language more or less specific as to structural and methodical features. It is to be understood, however, that the claims are not limited to the specific features shown and described, since the means herein disclosed comprise example embodiments. The claims are thus to be afforded full scope as literally worded, and to be appropriately interpreted in accordance with the doctrine of equivalents.

We claim:

1. An integrated assembly, comprising:
 - a first deck having first memory cells arranged in first tiers disposed one atop another;
 - a second deck over the first deck; the second deck having second memory cells arranged in second tiers disposed one atop another;
 - a third deck over the second deck; the third deck having third memory cells arranged in third tiers disposed one atop another;
 - a first feature passing through the first, second and third decks; the first feature having two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks; and
 - a second feature passing through the first, second and third decks; the second feature passing through the third memory cells of the third deck; the second feature having no inter-deck inflection associated with the boundary between the first and second decks.
2. The integrated assembly of claim 1 wherein the second feature comprises an inter-deck inflection associated with the boundary between the second and third decks.
3. The integrated assembly of claim 1 wherein the second feature comprises no inter-deck inflection associated with the boundary between the second and third decks.
4. The integrated assembly of claim 1 wherein the first feature comprises channel material.
5. The integrated assembly of claim 4 wherein the channel material comprises silicon.

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6. The integrated assembly of claim 4 wherein the first feature is a pillar.

7. The integrated assembly of claim 4 wherein the first feature is a hollow pillar.

8. The integrated assembly of claim 4 comprising charge-storage material adjacent the channel material.

9. The integrated assembly of claim 4 wherein the second feature does not comprise channel material.

10. The integrated assembly of claim 1 wherein the second feature comprises conductive material.

11. The integrated assembly of claim 1 wherein the second feature comprises insulative material.

12. The integrated assembly of claim 1 wherein the second feature is a pillar.

15. The integrated assembly of claim 1 wherein the second feature is a panel.

14. The integrated assembly of claim 1 wherein the second feature passes through the second memory cells of the second deck.

20. The integrated assembly of claim 1 wherein the second feature passes through the first memory cells of the first deck.

16. The integrated assembly of claim 1 wherein the second feature passes through the first, second and third memory cells of respective first, second, and third decks.

17. The integrated assembly of claim 1 wherein the second feature comprises insulative and conductive materials.

18. The integrated assembly of claim 1 wherein the first feature comprises a first side opposite a second side and the second feature extending along the first side of the first feature, and further comprising another second feature extending along the second side of the first feature.

19. The integrated assembly of claim 18 wherein the another second feature comprises insulative material.

20. The integrated assembly of claim 18 wherein the another second feature comprises insulative and conductive materials.

21. The integrated assembly of claim 1 wherein the first feature is a hollow pillar.

22. An integrated assembly, comprising:

a first deck having first memory cells arranged in first tiers disposed one atop another;

a second deck over the first deck; the second deck having second memory cells arranged in second tiers disposed one atop another;

a third deck over the second deck; the third deck having third memory cells arranged in third tiers disposed one atop another;

a first feature passing through the first, second and third decks; the first feature having two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks;

a second feature passing through the first, second and third decks; the second feature having no inter-deck inflection associated with the boundary between the first and second decks; and

wherein the second feature comprises an inter-deck inflection associated with the boundary between the second and third decks.

23. An integrated assembly, comprising:

a first deck having first memory cells arranged in first tiers disposed one atop another;

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a second deck over the first deck; the second deck having second memory cells arranged in second tiers disposed one atop another;

a third deck over the second deck; the third deck having third memory cells arranged in third tiers disposed one atop another;

a first feature passing through the first, second and third decks; the first feature having two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks;

a second feature passing through the first, second and third decks; the second feature having no inter-deck inflection associated with the boundary between the first and second decks;

wherein the first feature comprises channel material; and wherein the first feature is a hollow pillar.

24. An integrated assembly, comprising:

a first deck having first memory cells arranged in first tiers disposed one atop another;

a second deck over the first deck; the second deck having second memory cells arranged in second tiers disposed one atop another;

a third deck over the second deck; the third deck having third memory cells arranged in third tiers disposed one atop another;

a first feature passing through the first, second and third decks; the first feature having two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between

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the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks;

a second feature passing through the first, second and third decks; the second feature having no inter-deck inflection associated with the boundary between the first and second decks; and

wherein the second feature comprises insulative material.

25. An integrated assembly, comprising:

a first deck having first memory cells arranged in first tiers disposed one atop another;

a second deck over the first deck; the second deck having second memory cells arranged in second tiers disposed one atop another;

a third deck over the second deck; the third deck having third memory cells arranged in third tiers disposed one atop another;

a first feature passing through the first, second and third decks; the first feature having two inter-deck inflections, with one of said two inter-deck inflections of the first feature being associated with a boundary between the first and second decks, and with the other of said two inter-deck inflections of the first feature being associated with a boundary between the second and third decks;

a second feature passing through the first, second and third decks; the second feature having no inter-deck inflection associated with the boundary between the first and second decks; and

wherein the second feature is a panel comprising insulative and conductive material.

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